External Communications

Summary of Initiatives

MAY 2025

Annexure

Media Visibility

S.NO	Date	Publication	Headline	Page No	Link	AVE	Quote By
Exclusive Interview							
Print							
1	19th May	Business Standard	India targets 5% slice of global chip pie by '30	02	N/A	70000	Ashok Chandak
2	19th May	Business Standard (Hindi)	Target of a 5% share in the global chip market.	02	N/A	25000	Ashok Chandak
Exclusive Interaction							
Electronic Channel							
1	22nd May	CNBC International	India is a 'new frontier' for chip manufacturing, says, IESA President		Online	1443000	Ashok Chandak
2	22nd May	CNBC International	Inside India 22- 25	N/A	Online	1443000	Ashok Chandak
Exclusive Interaction							
Online							
1	16th May	Digitimes Asia	India's IESA targets global ties, skills push for chip growth	N/A	Online	86000	Ashok Chandak
Exclusive Interaction							
Print							

1	17th May	Business World	Soldering on as global chips demand surges, India's design-led startup seeks funds, mentorship, and infrastructure to stay in the race by Rohit Chintapali	66	N/A	120000	Ashok Chandak
Industry Story							
Print							
1	May	Fortune India	India and the world of Semiconductor manufacturing	56 - 60	N/A	1000000	Ashok Chandak
Industry Story – IESA & SEMI strengthen ECMS impact through strategic initiatives							
Print (Guwahati)							
1	27th May	Purvanchal Prahari	IESA SEMI welcomes the state government's initiative to promote ECMS	6	N/A	8500	Ashok Chandak
2	27th May	The North East Time	IESA & SEMI strengthen ECMS impact through strategic initiatives	2	N/A	12500	Ashok Chandak
3	27th May	Sentinel	IESA & SEMI strengthen ECMS impact through strategic initiatives	3	N/A	7500	Ashok Chandak
4	27th May	The Meghalaya Guardian	IESA SEMI welcomes the state government's initiative to promote ECMS	8	N/A	14000	Ashok Chandak
INDUSTRY STORY – India targets five per cent share in the global semiconductor market under Semicon 2.0							
PRINT							
1	20th May	Gujarat Samachar	India eyes 5% slice of global semiconductor chip pie by 2030	08	N/A	14500	Ashok Chandak
Industry Story – India targets five per cent share in the global semiconductor market under Semicon 2.0							
Online							
1.	21st May	Tele.net	India targets a five per cent share in the global semiconductor market under Semicon 2.0	N/A	Online	24000	Ashok Chandak
2	20th May	INVS News	India Targets 5% Share of Global Semiconductor Chip Production by 2030 with $10 Billion Investment	N/A	Online	35000	Ashok Chandak
Press Release – IESA announces new executive council, Ruchir Dixit Named as Chairperson for FY 2025 -26							
Online							
1	13th May	PV Magazine	India Electronics and Semiconductor Association announces new Executive Council, Ruchir Dixit Named as Chairperson for FY2025- 26	N/A	LINK	72000	Ashok Chandak
Industry Story – Cabinet approval for HCL – Foxconn OSAT joint venture a strategic milestone							
Electronics							
1	14th May	ET Now	Cabinet Nod For HCL-Foxconn Semicon Joint Venture	N/A	Online	74100	Ashok Chandak
Industry Story – HCL Foxconn display chip unit gets Govt Nod							
Print							
1	15th May	Mint	HCL Foxconn display chip unit gets Govt Nod	3	N/A	85000	Ashok Chandak
Print (National)							
1.	16th MAY	Business Remedies	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	07	N/A	12800	Ashok Chandak
2.	16th MAY	Dainik Bhor	HCL-Foxconn OSAT joint venture approved by the cabinet	02	N/A	5600	Ashok Chandak
3.	16th MAY	The Public Side	HCL-Foxconn OSAT joint venture gets cabinet approval, a strategic milestone	04	N/A	11000	Ashok Chandak
4.	16th MAY	Dainik Badhti Duniya	HCL-Foxconn OSAT joint venture gets cabinet approval: A strategic milestone.	04	N/A	7500	Ashok Chandak

5.	16th MAY	Dainik Dhola Maru	HCL-Foxconn OSAT joint venture receives cabinet approval, strategically a milestone.	02	N/A	8700	Ashok Chandak
6.	16th MAY	Dainik Taj Bharti	HCL-Foxconn OSAT joint venture receives cabinet approval, a strategic milestone	03	N/A	6700	Ashok Chandak
7.	16th MAY	Deccan Chronicle	India to drop tariffs on US imports, says Trump	10	N/A	28000	Ashok Chandak
8.	15th May	Mint	HCL-Foxconn display Chip unit gets govt nod	03	N/A	95000	Ashok Chandak
9.	15th May	Bizz Buz	India coming of age In semicon space	02	N/A	55000	Ashok Chandak
10.	15th May	The Hindu	India coming of age In semicon space	15	N/A	42000	Ashok Chandak
11.	15th May	The Telegraph	India coming of age In semicon space	11	N/A	39000	Ashok Chandak
12.	15th May	Business Remedies	HCL-Foxconn OSAT joint venture gets cabinet approval, a strategic milestone	07	N/A	35000	Ashok Chandak
13.	15th May	Dainik Adhika	HCL-Foxconn OSAT joint venture gets cabinet approval, strategically a milestone.	05	N/A	7400	Ashok Chandak
14.	15th May	Dainik News Jyoti	HCL-Foxconn OSAT Joint Venture Receives Cabinet Approval: A Strategic Milestone	05	N/A	4500	Ashok Chandak
15.	14th May	Business Standard	Centre gives nod to HCL-Foxconn chip unit	03	N/A	96000	Ashok Chandak
16.	14th May	Political & Business Daily	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	08	N/A	36000	Ashok Chandak
Print (Jaipur)							
1	15th May	Business Remedies	Cabinet approval for the HCL-Foxconn OSAT joint venture is a strategic milestone	07	N/A	25500	Ashok Chandak
2	15th May	Dainik Adhikar	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	05	N/A	8400	Ashok Chandak
3	15th May	Dainik News Jyoti	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	05	N/A	1000	Ashok Chandak
4	15th May	Uday Today	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	03	N/A	24000	Ashok Chandak
5	15th May	Dainik Bhor	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	02	N/A	17500	Ashok Chandak
6	15th May	The Public Side	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	04	N/A	7500	Ashok Chandak
7	15th May	Dainik Badti Duniya	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	04	N/A	8750	Ashok Chandak
8	15th May	Dainik Taj Bharti	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	03	N/A	16250	Ashok Chandak
9	15th May	Dainik Dhola Maru	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	02	N/A	6440	Ashok Chandak
10	16th May	Bureau Sandesh	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	02	N/A	7500	Ashok Chandak
11	16th May	Police Public Politics	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	02	N/A	8050	Ashok Chandak
12	16th May	Saccha Sagar	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	03	N/A	8280	Ashok Chandak

Print (Ahmedabad)							
1	16th May	Divya Gujarat	HCL-Foxconn OSAT joint venture gets Cabinet approval: Paving the way for India's semiconductor packaging leadership	03	N/A	8400	Ashok Chandak
2	15th May	Gujarat Pranam	HCL-Foxconn OSAT joint venture gets cabinet approval: Paves the way for India's leadership in semiconductor packaging.	02	N/A	9400	Ashok Chandak
3	15th May	Sabandh Bharat	HCL-Foxconn OSAT joint venture gets Cabinet approval: Clears the path for India's leadership in semiconductor packaging.	02	N/A	6400	Ashok Chandak
Print (Chennai)							
1.	19th May	Dina Kathir	HCL-Foxconn OSAT joint venture receives Union Cabinet approval: A significant milestone in India's semiconductor manufacturing journey under the strategic roadmap.	02	N/A	60000	Ashok Chandak
2.	19th May	Tamil Sudar	The HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	04	N/A	75000	Ashok Chandak
3.	19th May	Velli Ethal	The HCL-Foxconn plant reflects India's evolving maturity in semiconductor manufacturing.	03	N/A	60000	Ashok Chandak
4.	18th May	Dina Kural	The HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing.	04	N/A	75000	Ashok Chandak
5.	17thMay	News Today	HCL- Foxconn come together from semiconductor journey	03	N/A	75000	Ashok Chandak
6.	17th May	Trinity Mirror	HCL-Foxconn JV fills the gap for the semicon industry	06	N/A	75000	Ashok Chandak
7.	17th May	Business Minute	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	04	N/A	75000	Ashok Chandak
8.	17th May	Southern Mail	HCL-foxconn plant reflects India's growing maturity in the semiconductor industry manufacturing	03	N/A	75000	Ashok Chandak
9.	17th May	Virtual Times	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	02	N/A	64000	Ashok Chandak
Print – Gujarat							
1	16th May	Divya Gujarat	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	03	N/A	85800	Ashok Chandak
2	15th May	Gujarat Pranam	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	02	N/A	59100	Ashok Chandak
3	15th May	Sabandh Bharat	HCL-Foxconn plant reflects India's growing Maturity in semiconductor manufacturing	02	N/A	58800	Ashok Chandak

Industry Story – Cabinet Approval for HCL – Foxconn OSAT joint venture a strategic milestone							
Online							
1.	15th May	IANS Business	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	85000	Ashok Chandak
2.	15th May	The Hindu	Cabinet approves ₹3,700 crore display chip unit in Uttar Pradesh	N/A	Online	86000	Ashok Chandak
3.	15th May	Entrepreneur	Cabinet Approval of HCL-Foxconn JV a Fillip for Semicon Manufacturing in India	N/A	Online	7000	Ashok Chandak
4.	15th May	IT Voice	HCL-Foxconn Announces OSAT Joint Venture to Strengthen India's Semiconductor Ecosystem	N/A	Online	26000	Ashok Chandak
5.	15th May	Cellit	Cabinet Approves Rs 3,706 cr HCL-Foxconn Semiconductor Plant in Uttar Pradesh	N/A	Online	22000	Ashok Chandak
6.	15th May	Et Insight	Rs 3,700 Cr chip boost: India accelerates semiconductor push with new HCL–Foxconn unit in Uttar Pradesh	N/A	Online	75000	Ashok Chandak
7.	15th May	The Hindu	'Trump rhetoric won't harm Apple's India manufacturing'	N/A	Online	86000	Ashok Chandak
8.	14th May	Prokerala	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	23000	Ashok Chandak
9.	14th May	Hans India	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	70000	Ashok Chandak
10.	14th May	Social News XYZ	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	21000	Ashok Chandak
11.	14th May	Pune News	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	24000	Ashok Chandak
12.	14th May	Lokmat Times	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	24000	Ashok Chandak
13.	14th May	Ten News. in	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	23000	Ashok Chandak
14.	14th May	IANS live	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	85000	Ashok Chandak
15.	14th May	The Freedom Press	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	22000	Ashok Chandak
16.	14th May	The Hawk	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	23000	Ashok Chandak
17.	14th May	Outlook Business	Union Cabinet Approves India's Sixth Chip Unit Worth Rs 3,700 cr	N/A	Online	55000	Ashok Chandak
18.	14th May	The Hindu Business Line	Cabinet approves ₹3,700-crore HCL-Foxconn semiconductor unit in UP	N/A	Online	95000	Ashok Chandak
19.	14th May	Business Standard	Cabinet clears ₹3,706 cr HCL-Foxconn chip assembly unit at Jewar	N/A	Online	92000	Ashok Chandak
20.	14th May	Data Quest	HCL-Foxconn in OSAT joint venture	N/A	Online	35000	Ashok Chandak

21.	14th May	Democratic Jagat	Cabinet approval for HCL-Foxconn OSAT joint venture is a 16 strategic milestone	N/A	Online	24000	Ashok Chandak
22.	14thMay	Exclusive News	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	N/A	Online	23000	Ashok Chandak
23.	14th May	Divyarashtra	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	N/A	Online	21000	Ashok Chandak
24.	14th May	Bhaskar Live	HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	24000	Ashok Chandak
25.	14th May	Ajmernama	The HCL-Foxconn OSAT joint venture received Cabinet approval — a strategic milestone.	N/A	Online	23000	Ashok Chandak
26.	14th May	Deep Tech	Why India's Sixth Semiconductor Unit in UP Holds the Key Now	N/A	Online	35000	Ashok Chandak
27.	14th May	Daily hunt	HCL Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	21000	Ashok Chandak
28	14th May	Ajmer Nama	HCL Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	24000	Ashok Chandak
29	14th May	Divya Rashtra	HCL Foxconn plant reflects India's growing maturity in semiconductor manufacturing	N/A	Online	22000	Ashok Chandak
30	14th May	Exclusive News	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	N/A	Online	24000	Ashok Chandak
31	14th May	Democratic Jagat	Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone	N/A	Online	24000	Ashok Chandak
INDUSTRY STORY – The India – UK free trade agreement FTA							
Print – Jaipur							
1	8th May	Dainik Jalte Deep	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	7	N/A	1600	Ashok Chandak
2	8th May	Dainik Dhola Maru	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	2	N/A	7360	Ashok Chandak
3	8th May	Bureau Sandesh	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	2	N/A	8000	Ashok Chandak
4	8th May	Business Remedies	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	6	N/A	34500	Ashok Chandak
5	8th May	Dainik News Jyoti	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	5	N/A	7500	Ashok Chandak
6	8th May	Dainik Taj Bharti	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	3	N/A	6250	Ashok Chandak
7	8th May	Uday Today	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	4	N/A	24000	Ashok Chandak
8	8th May	Dainik Badti Duniya	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	4	N/A	20000	Ashok Chandak

9	8th May	Police Public Politics	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	2	N/A	13800	Ashok Chandak
10	8th May	Evening Post	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	7	N/A	7000	Ashok Chandak
11	8th May	The Public Side	The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products	4	N/A	1000	Ashok Chandak
ONLINE							
1	9th May	Democratic Jagat	The India–UK free trade agreement to enhance the export potential of 'Made in India' products	N/A	Online	24000	Ashok Chandak
2	7th May	Exclusive News	The India–UK free trade agreement to enhance the export potential of 'Made in India' products	N/A	Online	24000	Ashok Chandak
3	7th May	Divya Rashtra	The India–UK free trade agreement to enhance the export potential of 'Made in India' products	N/A	Online	22000	Ashok Chandak
4	7th May	Ajmer Nama	The India–UK free trade agreement to enhance the export potential of 'Made in India' products	N/A	Online	24000	Ashok Chandak
Industry Story – SEMI IESA applauds Tamil Nadu for the rapid follow-up policy of ECMS							
Print – Chennai							
1	3rd May	Dina Bhoomi	SEMI IESA lauds Tamil Nadu Government's Electronics Policy	4	N/A	60000	Ashok Chandak
2	2nd May	Tamil Sudar	SEMI IESA lauds Tamil Nadu Government's Electronics Policy	4	N/A	75,000	Ashok Chandak
3	2nd May	Virtual Times	SEMI IESA APPLAUDS TAMIL NADU FOR RAPID FOLLOW-UP POLICY OF ECMS	3	N/A	64,000	Ashok Chandak
4	2nd May	Malai Yugam	SEMI IESA lauds Tamil Nadu Government's Electronics Policy	3	N/A	60000	Ashok Chandak
5	2nd May	Dina Khatir	SEMI IESA Applauds Tamil Nadu for rapid follow-up policy of ECMS	2	N/A	60,000	
6	1st May	Dina Kural	SEMI IESA lauds Tamil Nadu Government's Electronics Policy	6	N/A	75,000	Ashok Chandak
7	1st May	Business Minutes	SEMI IESA Applauds Tamil Nadu for rapid follow-up policy of ECMS	4	N/A	75,000	Ashok Chandak
8	1st May	Southern Mail	Semi-iesa applauds Tamil Nadu for the rapid follow-up policy of ECMS	4	N/A	75,000	Ashok Chandak
Online							
1	2nd May	Chennai Glitz	SEMI IESA applauds Tamil Nadu for the rapid follow-up policy of ECMS	N/A	Online	35000	Ashok Chandak
2	1st May	Express News	SEMI IESA applauds Tamil Nadu for the rapid follow-up policy of ECMS	N/A	Online	24000	Ashok Chandak
3	30th April	The Times Of India	TN launches electronic components	N/A	Online	80000	Ashok Chandak

EXCLUSIVE INTERVIEW

PRINT

Date	19th May
Publication	Business Standard
Quote By	Ashok Chandak

India targets 5% slice of global chip pie by '30

Five cleared projects to push daily chip output to 91 million

SURAJEET DAS GUPTA
New Delhi, 18 May

The central government is aiming for a 5 per cent share of global semiconductor chip production by the end of 2030 as it readies for the next phase of the India Semiconductor Mission — Semicon 2.0. It has already committed disbursements from the $10 billion it earlier announced as incentives for prospective semiconductor fabrication (fab) players, as well as Outsourced Semiconductor Assembly and Test (OSAT) and Assembly, Testing, Marking, and Packaging (ATMP) companies. As many as five projects are already eligible under the scheme.

A senior official in the Ministry of Electronics and Information Technology (Meity) said: "We have just begun and have a long road ahead. We are aiming to achieve a 5 per cent share of global chip production capacity. A lot has to be done."

To achieve this target, Meity has already — according to the India Electronics & Semiconductor Association (IESA), the apex industry body — cleared projects with an aggregate capacity of over 75 million chips per day. If state-cleared projects are included, the number rises to 91 million chips per day.

Ashok Chandak, president of IESA and Semiconductor Equipment and Materials International (SEMI) India, said: "The projects cleared have a capacity of close to 75 million chips per day, from the five approved by Meity. There are others approved by states, which will add another 16 million chips a day. With this capacity, India will be able to meet a portion of its domestic demand and tap into the export market."

This is, of course, only the first stage.

Chip ambitions

Initial per day capacity of chip (in mn)

Tatas	48
HCL-Foxconn	1.2*
CG Power	15
Kaynes	6.3
Micron	4.8
Polymatech	6
Suchi Semicon	10
RRP Electronics & RIR	

*36 million capacity per month
Sources: Company, IESA, industry estimates

The state projects include Suchi Semicon in Gujarat, RRP Electronics in Maharashtra, and RIR Power Electronics in Odisha, which will collectively produce 10 million chips per day once operational. Polymatech Electronics, based in Chennai, is already operational and currently has a capacity of 6 million chips per day, with another plant being set up in Chhattisgarh.

Then there is Micron, which is expected to roll out its first Make in India chips by the end of this year. While it has not officially announced its capacity, industry sources say it will be around 4.8 million chips per day.

According to SEMI's World Fab Forecast (the global semiconductor association body), global fab capacity reached 31 million wafers per month in 2024. "This capacity, measured in terms of 200 millimetre-equivalent wafers, translates into roughly 1 million wafers per day," said Ajit Manocha, president of SEMI Global.

Under Semicon 2.0, the focus will also be on expanding the ecosystem — which includes the global supply chain of specialised chemicals, gases, and other inputs required for fab manufacturing. Building this ecosystem is key to expanding chip-making capacity.

India, of course, faces competition. Malaysia currently holds about 14 per cent of the global OSAT market, while Taiwan controls more than 40 per cent. In an interview last year, Meity Minister Ashwini Vaishnaw said the ambition is to capture 25 per cent of the ATMP/OSAT global market over the next 10 years.

The total investment across the six upcoming plants is over ₹1.55 trillion, with the bulk — ₹91,000 crore — going to the Tata fab plant. The remaining five projects are in the OSAT and ATMP space, where the final Make in India chips will be rolled out.

Date	19th May
Publication	Business Standard (Hindi)
Quote By	Ashok Chandak

वैश्विक चिप बाजार में 5 फीसदी हिस्से का लक्ष्य

सरकार साल 2030 के आखिर तक कुल वैश्विक सेमीकंडक्टर चिप उत्पादन की 5 फीसदी हिस्सेदारी हासिल करने का लक्ष्य रख रही है। भारतीय सेमीकंडक्टर योजना 2.0 के अगले चरण के लिए तैयार है। सरकार पहले ही 10 अरब डॉलर के आवंटन की प्रतिबद्धता जता चुकी है। यह राशि सेमीकॉन फैब के संभावित भागीदारों के साथ-साथ ओएसएटी और एटीएमपी कंपनियों को प्रोत्साहन के रूप में दी जाएगी। इस योजना के तहत पहले ही करीब पांच परियोजनाएं पात्र हैं। इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय के वरिष्ठ अधिकारी ने कहा कि हमारा लक्ष्य वैश्विक चिप उत्पादन क्षमता का 5 फीसदी हिस्सा हासिल करना है।

पृष्ठ 2

EXCLUSIVE INTERACTION

ELECTRONIC CHANNEL

Date	22nd May
Publication	CNBC International
Link	https://www.cnbc.com/video/2025/05/22/india-is-aa-new-frontiera-for-chip-manufacturing-says-iesa-president.html?qsearchterm=Ashok%20Chandak%20

Date	22nd May
Publication	CNBC International
Link	https://www.youtube.com/live/rWZK8-rApR4

EXCLUSIVE INTERACTION

Date	16th May
Publication	DigiTimes Asia
Link	https://www.digitimes.com/news/a20250514VL207/iesa-design-technology-development-market.html

India's IESA targets global ties, skills push for chip growth

Prasanth Aby Thomas, DIGITIMES, Bangalore | Friday 16 May 2025 | 0 | Like 0

The India Electronics and Semiconductor Association (IESA) is accelerating its multi-pronged strategy to develop the country's semiconductor value chain, expanding cross-border industry collaborations while advancing state-level partnerships and workforce development programs.

Speaking to *DIGITIMES* Asia, IESA President Ashok Chandak said the group is doubling down on international cooperation, emphasizing firm-to-firm collaborations and technology transfer opportunities over traditional government-led negotiations.

"We strongly believe these international cooperations are a must, particularly for India's manufacturing sector, because we don't yet have the mature processes or technology for mass semiconductor production - whether it's foundry or OSAT," said Chandak, who is also the president of Semi India. "Through our MoUs with multiple global industry bodies, we are working to attract companies to set up operations, form joint ventures, or engage in technology transfer activities."

In March 2025, IESA organized roundtables with delegations from countries like Korea, Taiwan, Singapore, Malaysia, Sweden, the Netherlands, and the US at its Vision Summit in Gandhinagar. A follow-up webinar with Malaysia's semiconductor association, economic development agency, and embassy was conducted in April 2025. More such bilateral engagements are expected in the coming months.

"We focus on industry-level engagements. Government dialogue happens through ministries like MEITY or External Affairs. We join those, when necessary, but our priority is enabling the ecosystem through industry bodies," Chandak explained.

Manufacturing momentum

India's OSAT and ATMP landscape is gaining traction, with projects by Micron, Kaynes, CG Power, Sahasra, and others progressing across Gujarat, Bhiwadi, Surat, and Chennai. Notably, Tata has announced plans for the country's first full-scale foundry.

"This year, we see it as quite realistic that the first Made-in-India packaged chips —particularly from the ATMP and OSAT facilities — will reach the market," Chandak said. "That will be a milestone and a proof-of-the-pudding moment for India's semiconductor aspirations."

IESA is also tracking new proposals under evaluation by states and expects the central government to soon announce a second phase of incentives under "Semicon India 2.0."

Design-to-product transition

On the design front, about 12 startups have secured financial backing under the Design Linked Incentive (DLI) scheme, and several teams are accessing EDA tools under the Chip-to-Startup (C2S) initiative. Multinationals like NXP and Infineon are also expanding captive design centers.

"We've submitted a report to the government recommending that India focus on product creation as the next big step. That's where most of the profit and economic value lies," Chandak said, adding that this recommendation has been shared with the government.

Skill-building initiatives

To meet the industry's demand for skilled labor, IESA launched a pilot ATMP skilling program in Gandhinagar in April 2025. It plans to scale up training initiatives nationally in collaboration with SEMI.

"We have a strategic alliance with SEMI, and we're launching multiple training programs using their global curriculum. This includes manufacturing skills as well as design and R&D-focused education with the Indian Design and Packaging Systems Initiative (IDPS)," Chandak said.

IESA is also advising several states — including Karnataka, Gujarat, Madhya Pradesh, Odisha, Chhattisgarh, and Maharashtra — on policy formulation, investment facilitation, and ecosystem readiness. "We participate in approval committees and help shape state-level policy frameworks. It's about ensuring states develop relevant clusters, not just infrastructure," Chandak added.

Growing market, expanding opportunity

India's domestic semiconductor demand is projected to reach around US$103 billion by 2030. Globally, the chip market, valued at just under US$600 billion in 2023, is expected to cross US$1 trillion by the end of the decade.

"There's enough opportunity for every region to contribute," Chandak said. "India offers a vibrant design ecosystem and a massive captive market. Our focus should be on leveraging these strengths."

IESA will showcase ongoing initiatives at Semicon Southeast Asia in Singapore this May 2025 and the flagship Semicon India event in New Delhi in September 2025.

EXCLUSIVE INTERACTION

PRINT

Date	17th May
Publication	Business World
Quote By	Ashok Chandak

SOLDERING ON

As global chip demand surges, India's design-led startups seek funds, mentorship, and infrastructure to stay in the race By Rohit Chintapali

INDIA'S semiconductor startups are standing at the edge of a trillion-dollar global opportunity but without enough capital to leap. Despite a wealth of engineering talent at home and maturing government support, these fabless chip ventures face a daunting combination of chronic underfunding and misaligned venture capital expectations.

With international peers raising tens of millions in early rounds, Indian startups are often left struggling with sub-$3 million deals to build complex System-on-Chip (SoC) products. Coupled with longer R&D cycles and high upfront costs, the traditional VC playbook built for SaaS or consumer tech simply doesn't translate. As founders push forward against structural and ecosystem gaps, many believe bold, patient capital and deeper strategic support are the only way to level the playing field.

Capital Constraints

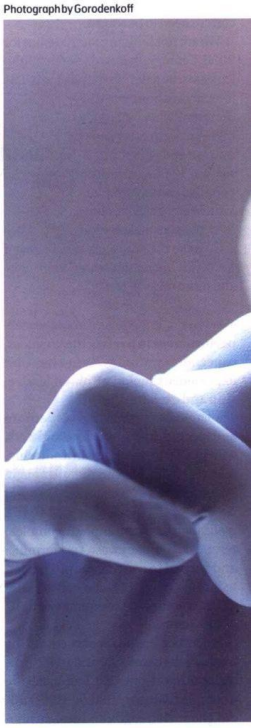
Indian semiconductor startups battle a severe funding disadvantage compared to global peers, with domestic investments falling far short of international benchmarks.

"Access to risk capital remains the top priority for Indian startups, especially in the fabless semiconductor sector," says Ashok Chandak, President, India Electronics and Semiconductor Association (IESA). "Developing a typical simpler function System-on-Chip (SoC) requires nearly $10 million for R&D and another $10 million for sales and marketing. However, most Indian deals are significantly smaller – often below $3 million." The funding gap becomes stark in global comparisons. "A similar CPU core company in the Bay Area could raise anywhere from $50 million to $100 million. Competing globally becomes incredibly challenging under such resource constraints," Chandak adds.

This disparity is worsened by a fundamental mismatch between semiconductor development timelines and traditional venture capital expectations. Sunil Shekhawat, CEO at SanchiConnect, explains: "These ventures often require longer R&D cycles and significantly higher capital compared to SaaS or consumer startups. This creates a misalignment with traditional VC expectations, especially around exit timelines and capital efficiency."

According to industry reports, semiconductor startups in India collectively raised approximately $28 million in 2024, the highest annual funding recorded for the sector so far. Recent funding recipients include FermionIC, Agnit Semiconductors, Morphing Ma-

Photograph by Gorodenkoff



Industry Story – IESA & SEMI strengthen ECMS impact through strategic initiatives

PRINT – GUWHATI

Date	27th May
Publication	Purvanchal Prahari
Quote By	Ashok Chandak

आईईएसए और सेमी ईसीएमएस के प्रभाव को मजबूत करेंगे

नई दिल्ली : आईईएसए और सेमी असम सरकार को राज्य में इलेक्ट्रॉनिक्स कम्पोनेंट मैन्युफैक्चरिंग स्कीम (ईसीएमएस) को बढ़ावा देने में अपनी केंद्रित रणनीति के लिए बधाई देते हैं। यह पहल भारत की इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग क्षमताओं को आगे बढ़ाने और घरेलू मूल्य संवर्धन को बढ़ाने में एक महत्वपूर्ण कदम का प्रतिनिधित्व करती है, जो भारत के उत्तर-पूर्वी क्षेत्र में राष्ट्रीय सेमीकंडक्टर नीति और विकास का पूरक है। आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने प्रमुख मेम्बर लीडरों के साथ, असम के मुख्यमंत्री डॉ. हिमंत विश्व शर्मा की गरिमामयी उपस्थिति में नई दिल्ली में आयोजित असम इलेक्ट्रॉनिक्स राउंड टेबल 2025 में भाग लिया। गोलमेज सम्मेलन के दौरान और उसके बाद वरिष्ठ राज्य अधिकारियों के साथ हुई बैठकों में बोलते हुए, चांडक ने ईसीएमएस के वैश्विक प्रभाव को अधिकतम करने के लिए सेमी और आईईएसए की बहुआयामी रणनीति पर जोर दिया। इनमें टेक्नोलॉजी तक पहुंच के लिए अंतर्राष्ट्रीय सहयोग को बढ़ावा देना, स्थानीय रूप से उत्पादित कम्पोनेंट्स को बढ़ावा देने के लिए वितरकों को शामिल करना और देश में निर्मित कम्पोनेंट्स में निवेश करने और उनका उपयोग करने के लिए ईएमएस और ओईएम कंपनियों का समर्थन करना शामिल है।

Date	27th May
Publication	The North East Times
Quote By	Ashok Chandak

IESA and SEMI to strengthen ECMS impact through strategic initiatives

GUWAHATI, MAY 26: IESA and SEMI congratulate the Government of Assam for its focused strategy in promoting the Electronics Components Manufacturing Scheme (ECMS) in the state. This initiative represents a pivotal step in advancing India's electronics manufacturing capabilities and enhancing domestic value addition, complementing the national semiconductor policy and development in north north-east region of India

Ashok Chandak, President of IESA and SEMI India, along with key member leaders, participated in the Assam Electronics Round Table 2025 held in New Delhi in the esteemed presence of Dr. Himanta Biswa Sarma, Chief Minister of Assam.

Speaking during the roundtable and in subsequent one-on-one meetings with senior state officials, Chandak emphasized IESA and SEMI's multi-pronged strategy to maximize the global impact of the ECMS. These include fostering international collaborations for technology access, engaging distributors to promote locally produced components, and supporting EMS and OEM companies to invest in and utilize domestically manufactured components. Assam's ECMS policy Simone is one of the best with 60% top up incentives and additional incentive's and support thru ongoing schemes for ESDM.

"SEMI, IESA and our member companies are fully committed to amplifying the ECMS initiative, driving India toward becoming a global leader in electronics and semiconductors," said Chandak. "With the powerful combination of the ECMS Production Linked Incentive (PLI) scheme, the Semicon India program, and progressive state government policies, India is poised to build a globally competitive and resilient electronics manufacturing ecosystem." NET STAFFER

Date	27th May
Publication	Sentinel
Quote By	Ashok Chandak

आईईएसए और सेमी रणनीतिक पहलकदमियों करेंगे ईसीएमएस के प्रभाव को मजबूत

गुवाहाटी, 26 मई (एसं)। आईईएसए और सेमी असम सरकार को राज्य में इलेक्ट्रॉनिक्स कम्पोनेंट मैन्युफैक्चरिंग स्कीम (ईसीएमएस) को बढ़ावा देने में अपनी केंद्रित रणनीति के लिए बधाई देते हैं। यह पहल भारत की इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग क्षमताओं को आगे बढ़ाने और घरेलू मूल्य संवर्धन को बढ़ाने में एक महत्वपूर्ण कदम का प्रतिनिधित्व करती है, जो भारत के उत्तर-पूर्वी क्षेत्र में राष्ट्रीय सेमीकंडक्टर नीति और विकास का पूरक है। आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने प्रमुख मेम्बर लीडरों के साथ, असम के माननीय मुख्यमंत्री डॉ. हिमंत विश्व शर्मा की गरिमामयी उपस्थिति में नई दिल्ली में आयोजित असम इलेक्ट्रॉनिक्स राउंड टेबल 2025 में भाग लिया। गोलमेज सम्मेलन के दौरान और उसके बाद वरिष्ठ राज्य अधिकारियों के साथ हुई बैठकों में बोलते हुए, श्री चांडक ने ईसीएमएस के वैश्विक प्रभाव को अधिकतम करने के लिए सेमी और आईईएसए की बहुआयामी रणनीति पर जोर दिया। इनमें टेक्नोलॉजी तक पहुंच के लिए अंतर्राष्ट्रीय सहयोग को बढ़ावा देना, स्थानीय रूप से उत्पादित कम्पोनेंट्स को बढ़ावा देने के लिए वितरकों को शामिल करना और देश में निर्मित कम्पोनेंट्स में निवेश करने और उनका उपयोग करने के लिए ईएमएस और ओईएम कंपनियों का समर्थन करना शामिल है। असम की ईसीएमएस नीति सिमोन सर्वश्रेष्ठ नीतियों में से एक थी, इसके तहत 60 प्रतिशत टॉप-अप इन्सेंटिव और अतिरिक्त इन्सेंटिव की व्यवस्था थी, तथा ईएसडीएम के लिए जारी योजनाओं के जरिए यह सहयोगकारी थी। श्री चांडक ने कहा, सेमी आईईएसए और हमारी सदस्य कंपनियां ईसीएमएस पहल को आगे बढ़ाने के लिए पूरी तरह प्रतिबद्ध हैं, जिससे भारत इलेक्ट्रॉनिक्स और सेमीकंडक्टर में वैश्विक लीडर बनने की दिशा में आगे बढ़ रहा है। ईसीएमएस उत्पादन से जुड़ी प्रोत्साहन (पीएलआई) योजना, सेमीकॉन इंडिया कार्यक्रम और प्रगतिशील राज्य सरकार की नीतियों के शक्तिशाली संयोजन के साथ, भारत वैश्विक रूप से प्रतिस्पर्धी और लचीला इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग ईकोसिस्टम बनाने के लिए तैयार है।

Date	27th May
Publication	The Assam Tribune
Quote By	Ashok Chandak

IESA, SEMI welcome State govt initiative to promote ECMS

GUWAHATI, May 26: Congratulating the Government of Assam for its focused strategy in promoting the Electronics Components Manufacturing Scheme (ECMS) in the State, IESA and SEMI stated that this initiative represents a pivotal step in advancing India's electronics manufacturing capabilities and enhancing domestic value addition, complementing the national semiconductor policy and development in northeastern region of India.

Ashok Chandak, President of IESA and SEMI India, along with key member leaders, participated in the Assam Electronics Round Table 2025 held in New Delhi in the presence of Chief Minister Dr Himanta Biswa Sarma, stated a press release.

Speaking during the roundtable and in subsequent one-on-one meetings with senior State officials, Chandak emphasized IESA and SEMI's multi-pronged strategy to maximize the global impact of the ECMS. These include fostering international collaborations for technology access, engaging distributors to promote locally-produced components, and supporting EMS and OEM companies to invest in and utilize domestically manufactured components. Assam's ECMS policy is one of the best with 60% top up incentives and additional incentives and support through ongoing schemes.

"SEMI, IESA and our member companies are fully committed to amplifying the ECMS initiative, driving India toward becoming a global leader in electronics and semiconductors," said Chandak. "With the powerful combination of the ECMS Production Linked Incentive (PLI) scheme, the Semicon India programme, and progressive State government policies, India is poised to build a globally competitive and resilient electronics manufacturing ecosystem," he said.

Date	27th May
Publication	The Meghalaya Guardian
Quote By	Ashok Chandak

IESA and SEMI to strengthen ECMS impact through strategic initiatives

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INDUSTRY STORY - India Targets Five Per Cent Share In The Global Semiconductor Market Under Semicon 2.0

PRINT

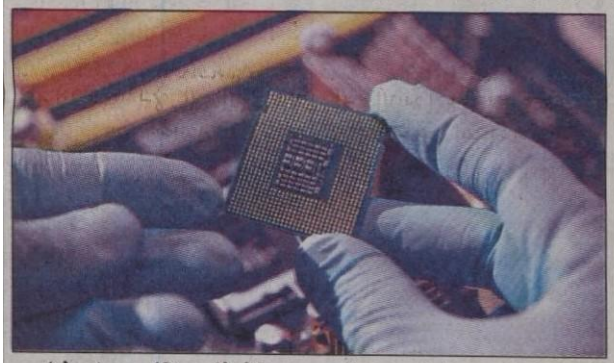
Date	20th May
Publication	Gujarat Samachar
Quote By	Ashok Chandak

૨૦૩૦ સુધીમાં વૈશ્વિક સેમિકન્ડક્ટર ચિપ ઉત્પાદનમાં ૫% હિસ્સો હાંસલ કરવાનો લક્ષ્યાંક

અમદાવાદ, તા. ૧૯

સરકાર ૨૦૩૦ના અંત સુધીમાં કુલ વૈશ્વિક સેમિકન્ડક્ટર ચિપ ઉત્પાદનમાં ૫ ટકા હિસ્સો હાંસલ કરવાનું લક્ષ્ય રાખે છે. આ માટે, તે ભારતીય સેમિકન્ડક્ટર યોજના ૨.૦ના આગામી તબક્કાની તૈયારી કરી રહી છે. તેણે જાહેરાત કરેલા ૧૦ બિલિયન ડોલરનું વિતરણ કરવા માટે તેણે પહેલાથી જ પ્રતિબદ્ધતા વ્યક્ત કરી છે. આ રકમ પ્રોત્સાહન તરીકે આપવામાં આવશે. આ યોજના હેઠળ લગભગ પાંચ પ્રોજેક્ટ પહેલાથી જ પાત્ર હોવાનું જાણવા મળ્યું છે.

અત્યાર સુધીમાં દરરોજ ૭૫ મિલિયનથી વધુ ચિપ્સનું ઉત્પાદન કરવાની ક્ષમતા ધરાવતા પ્રોજેક્ટ્સને મંજૂરી



ઉદ્યોગસંગઠન, ઇન્ડિયન ઇલેક્ટ્રોનિક્સ એન્ડ સેમિકન્ડક્ટર અનુસાર, મંત્રાલયે અત્યાર સુધીમાં તેના લક્ષ્યને પ્રાપ્ત કરવા માટે દરરોજ ૭૫ મિલિયનથી વધુ ચિપ્સનું ઉત્પાદન કરવાની કુલ ક્ષમતા ધરાવતા પ્રોજેક્ટ્સને મંજૂરી આપી છે. જોકે, જો રાજ્યો દ્વારા મંજૂર કરાયેલા પ્રોજેક્ટ્સને પણ આ સંખ્યામાં ઉમેરવામાં આવે, તો તે દરરોજ ૯.૧ કરોડ ચિપ્સ સુધી પહોંચી જશે. ઈલેક્ટ્રોનિક્સ અને માહિતી ટેકનોલોજી મંત્રાલય દ્વારા મંજૂર કરાયેલા પાંચ પ્રોજેક્ટ્સમાંથી મંજૂર કરાયેલા પ્રોજેક્ટ્સની ક્ષમતા દરરોજ લગભગ ૭૫ મિલિયન ચિપ્સ છે.

રાજ્યના પ્રોજેક્ટ્સમાં ગુજરાતમાં સુચી સેમિકોન, મહારાષ્ટ્રમાં આરઆરપી ઇલેક્ટ્રોનિક્સ, ઓરિસ્સામાં આરઆઈઆરનો સમાવેશ થાય છે. એકવાર કાર્યરત થયા પછી, આ સામૂહિક રીતે દરરોજ દસ મિલિયન ચિપ્સનું ઉત્પાદન કરશે. પોલીમેટેક, ચેન્નાઈ પહેલેથી જ કાર્યરત છે. હાલમાં, તેની ક્ષમતા દરરોજ ૬૦ લાખ ચિપ્સની છે. છત્તીસગઢમાં બીજો પ્લાન્ટ સ્થાપિત થઈ રહ્યો છે. માઈક્રોન પણ આ સ્પર્ધામાં છે અને આ વર્ષના અંતમાં તેની પહેલી મેડ-ઈન-ઈન્ડિયા ચિપ્સ લોન્ચ કરે તેવી અપેક્ષા છે.

INDUSTRY STORY - India Targets Five Per Cent Share In The Global Semiconductor Market Under Semicon 2.0

ONLINE

Date	21th May
Publication	Tele.net
Link	https://tele.net.in/india-targets-five-per-cent-share-in-the-global-semiconductor-market-under-semicon-2-0/

India targets five per cent share in the global semiconductor market under Semicon 2.0

May 21, 2025 | Miscellaneous, News

The government of India is aiming to capture five per cent of the global semiconductor manufacturing market by 2030 as it gears up for the next phase of its semiconductor initiative, Semicon 2.0. It has already committed disbursements from the $10 billion it earlier announced as incentives for prospective semiconductor fab players, as well as outsourced semiconductor assembly and test (OSAT) and assembly, testing, marking and packaging (ATMP) companies. So far, five projects have been deemed eligible under the scheme.

According to the India Electronics & Semiconductor Association (IESA), to achieve this target, the Ministry of Electronics and Information Technology (MeitY) has cleared projects with a cumulative capacity to produce over 75 million chips per day. Including state-cleared projects, this total rises to 91 million chips per day.

State-backed projects include Suchi Semicon in Gujarat, RRP Electronics in Maharashtra, and RIR Power Electronics in Odisha, which are together expected to produce 10 million chips per day, once it gets operational. Further, Chennai-based Polymatech Electronics is already active, with a current capacity of 6 million chips daily and a new plant is also under development in Chhattisgarh.

Additionally, Micron is expected to roll out its first 'Make in India' chips by the end of 2025, with the industry estimating its daily output to be around 4.8 million chips.

Further, under Semicon 2.0, the government will also prioritise building a robust semiconductor ecosystem, including supply chains for specialised chemicals, gases, and other essential materials, critical to sustaining and scaling domestic chip manufacturing.

India, naturally, faces competition. Malaysia currently accounts for around 14 per cent of the global OSAT market, while Taiwan holds over 40 per cent. Furthermore, last year, Ashwini Vaishnaw, Union Minister for Electronics and Information Technology, Information and Broadcasting, and Railways, had said that the goal is to secure 25 per cent of the global ATMP/OSAT market within the next decade.

Date	20th May
Publication	INVC News
Link	https://internationalnewsandviews.com/india-semiconductor-production-5-percent-2030-10-billion-investment-386623-2/

India Targets 5% Share of Global Semiconductor Chip Production by 2030 with $10 Billion Investment

By **INVC Desk** - May 20, 2025

INVC NEWS

New Delhi — : India is aggressively pursuing a 5 percent share of the global semiconductor chip manufacturing market by 2030 through its ambitious Indian Semiconductor Scheme 2.0. The government has already committed $10 billion in incentives to attract semiconductor fabrication (fab) units, OSAT (Outsourced Semiconductor Assembly and Test), and ATMP (Assembly, Testing, Marking, and Packaging) companies to boost domestic production and strengthen the electronics ecosystem. Five key projects have been approved under this scheme, marking a strong start towards achieving the country's semiconductor ambitions.

A senior official from the Ministry of Electronics and Information Technology stated, "Our journey has just begun, but our commitment to reach 5 percent of global chip production capacity remains firm. Much work lies ahead to realize this vision."

The Indian Electronics and Semiconductor Association (IESA) highlights that approved projects currently account for a production capacity of over 75 million chips per day. When combined with state-approved initiatives, this capacity is set to grow to approximately 91 million chips daily. Notable state-level projects include Suchi Semicon in Gujarat, RRP Electronics in Maharashtra, and RIR in Odisha, which are expected to collectively contribute an additional 10 million chips daily upon completion.

Industry leaders emphasize that these efforts not only aim to fulfill growing domestic semiconductor demand but also position India as a significant player in the global export market. Major players like Micron are also gearing up to launch their first made-in-India chips, with expected capacities nearing 4.8 million chips per day.

Semiconductor Scheme 2.0 will additionally focus on expanding India's semiconductor ecosystem, including securing key components like specialized chemicals and gases essential for fab construction and operation. Strengthening the entire supply chain is critical to scaling chip production capacity to meet both national and international needs.

With strategic investments and ecosystem development, India is set to become a semiconductor manufacturing hub, boosting technological self-reliance and contributing significantly to the global chip supply by 2030.

Press Release - IESA announces new Executive Council, Ruchir Dixit Named as Chairperson for FY2025- 26

Date	13th May
Publication	PV Magazine
Link	https://www.pv-magazine-india.com/press-releases/india-electronics-and-semiconductor-association-announces-new-executive-council-ruchir-dixit-named-as-chairperson-for-fy2025-26/

India Electronics and Semiconductor Association announces new Executive Council, Ruchir Dixit Named as Chairperson for FY2025- 26

Dixit brings over 30 years of global leadership experience in both semiconductor and electronic design automation (EDA) industry. He currently serves as the Vice President and Country Manager at Siemens EDA India.

MAY 13, 2025 IESA

Share

The India Electronics and Semiconductor Association (IESA), the premier industry body representing the ESDM sector in India, announced the new Executive Council and appointment of **Mr. Ruchir Dixit as the Chairperson for the FY2025- 26 term.** This announcement was made today at the IESA Annual Members Meeting, at Taj West End, Bengaluru attended by over 200 members and VIP dignitaries.

Mr. Dixit brings over **30 years of global leadership experience** in both semiconductor and electronic design automation (EDA) industry. He currently serves as the **Vice President and Country Manager at Siemens EDA India**. Dixit's appointment and New EC announcement comes at a time when India is taking giant leaps in semiconductor and electronics design led manufacturing.

Prior to his new role as Chairperson, Mr. Dixit was Vice Chairman of IESA and has played pivotal role in shaping the IESA community. With broad experience across product engineering, strategic alliances and technology innovation, Ruchir Dixit previously served senior leadership positions at **Mentor Graphics**. Ruchir Dixit is an alumnus of Wayne State University, Michigan and Haas School of Business at University of Berkeley

Speaking on his appointment as the newly appointed Chairperson of IESA, Mr. Ruchir Dixit said:

"India is at a crucial juncture today. There is an opportunity to become a global powerhous in the global ecosystem of Electronics and Semiconductors. The responsibility given to me by the IESA members to lead the industry body is a great privilege for me. IESA represents the entire ecosystem and has always been at the forefront of the sector in fostering innovation, policy, and collaboration. IESA will work with all the stakeholders – Member companies, Government of India & various State Governments and its partners to drive an accelerate the three goals – Make India a **Product Nation**, Make a **Production Nation** and Make India the **Skills Nation** – for India and for the world."

Welcoming Mr. Dixit, Mr. Ashok Chandak, President of IESA, said: "We are delighted to welcome Mr. Ruchir Dixit as the Chairperson of IESA, along with the new Executive Council. As we continue to establish India as a global leader in the semiconductor industry, his extensive industry experience will be crucial in guiding our efforts. The association is today seen as the predominant voice of the industry and plays a crucial role in India's ESDM ecosystem. We look forward to the Executive Council's leadership and contributions in advancing IESA's efforts towards growth and innovation in the sector."

Six new leaders were elected to the Executive Council, including **Mr. Akshay Aggarwal, Senior Director of Engineering , MediaTech ; Dr. Hemang Shah, Senior Director Government Affairs, Applied Materials; Mr. Pradeep Kumar Vajram, Managing Partner 7Rays; Mr. Raghu Panicker, Chief Executive Officer, Kaynes SemiCon; Mr. Sundeep Gupta, MD India & VP Central R&D, Alphawave Semi,** and Mr. **Vivek Tyagi, Managing Director of Sales, Analog Devices. Continuing EC members from last year are : Navin Bishnoi (Elected as Vice Chairperson), Rajeev Khushu, Sanjeev Keskar (Elected as Treasurer), Dr. Veerappan VV (Advisor) and Ashok Chandak (President).**

Furthermore, IESA is immensely grateful to **Dr. V Veerappan,** the former Chairperson, for his transformative leadership, vision and accomplishments during his term which set a new benchmark for the industry. He will take the role of an advisor to the IESA Executive Council and continue to advance the association's ambitions through the ongoing initiatives.

The event was graced by several eminent industry leaders and government officials. The **Chief Guest, Shri S. Krishnan, IAS, Secretary, MeitY, Government of India,** delivered an engaging and inspiring keynote on India's semiconductor roadmap and the importance of innovation and policy collaboration. The Guests of Honor included, **Mr. Ajit Manocha, CEO & President, SEMI, Shri Tejasvi Surya, Member of Parliament, Bengaluru South Lok Sabha Constituency; Shri S.K. Bache Gowda, Chairman, KEONICS and Hon'ble MLA, Hosakote Assembly Constituency**; and **Prof Rao Tummala, Advisor ISM and Professor Emeritus GeorgiaTech, USA,** each offering valuable perspectives on the evolving ESDM ecosystem.

With this fresh leadership, IESA reaffirms its dedication to promoting industry partnerships, talent development and innovations that will enable India's semiconductor and electronics sector to flourish.

About IESA

IESA is India's premier industry body for ESDM & Intelligent Electronics. Our main objective is to establish India as a leading global hub for electronics manufacturing and design. We work with government ministries, industry players, and academic institutions to facilitate the comprehensive implementation of the Program for Development of Semiconductor and Display Ecosystem. Our team of renowned experts in semiconductor and display technologies is committed to promoting technology solutions that positively impact the lives of 1.3 billion Indians.

INDUSTRY STORY – HCL Foxconn Display Chip Unit Gets Govt Nod

Print

Date	15th May
Publication	Mint
Quote By	Ashok Chandak

HCL-Foxconn display chip unit gets govt nod

₹3,700 cr project India's first display chip testing & manufacturing facility

Priyanka Sharma & Shouvik Das
NEW DELHI

India's display manufacturing industry received a boost on Wednesday when the Union cabinet approved the India Semiconductor Mission's (ISM) fourth chip-testing facility and the fifth semiconductor project overall.

The ₹3,700-crore (around $433 million) project, first floated in January 2024, is an outsourced semiconductor assembly and testing (Osat) facility being developed by IT services firm HCL Technologies Ltd in partnership with Taiwanese contract manufacturer Hon Hai Precision Industry Co. Ltd, better known as Foxconn.

However, the HCL-Foxconn joint venture is the first "advanced manufacturing Osat" in the country, catering specifically to displays, making it the first chip-testing project of its kind. It will help the country localise the manufacturing of displays used in mobile phones and laptops, a senior official with direct knowledge of the matter told *Mint* seeking anonymity. The unit, expected to be operational by 2027, will aim to produce 36 million chips a month by processing 20,000 semiconductor wafers.

The fifth OSAT facility in India comes as the semiconductor sector awaits cabinet approval for the second tranche of ISM incentives of up to $20 billion, aimed at supporting a $500-billion electronics economy over the next five years.

Mint reported in September that incentives may focus more on chip and display fabs than on Osat projects. However, the HCL-Foxconn Osat is in line with the overall strategy of the ISM second phase, said industry experts.

While chip-testing plants are typically of low margin and value, "the ideal strategy to set up Osats in India would either be to partner with a world-class chip and electronics brand that has existing clients and can draw business to the country, or for new forms of technology that will contribute to increasing value addition in new product categories," Jasbir Singh Gujral, managing director of electronics manufacturing firm Syrma SGS Technology Ltd, told *Mint*. It will be the first unit to help India localise display manufacturing.

HCL-Foxconn's facility under ISM scheme is likely to be operational by 2027. MINT

STACKING THE CHIPS

IT is India's 4th Osat project and 5th semiconductor unit with a focus on localising chip manufacturing.

THE plant will make complex display driver ICs and higher per-chip value than general-purpose ICs.

HCL, Foxconn team up to bring global clients and tech—a model key to Osat success in India.

This, though, is not the same as a display fabrication plant, which is responsible for the end-to-end manufacturing of the semiconductor components of a display. It is what generates the second-highest percentage of domestic value for products such as smartphones and laptops (apart from the primary processor itself).

But, according to stakeholders, it is also highly complex and costly to establish. "Besides, the HCL-Foxconn project will produce high-value display driver integrated circuits (DDICs). They are far more complex devices than general-purpose ICs that the likes of Tata Electronics Osat will produce, which will deliver higher per-chip dollar value," said Ashok Chandak, president of India Electronics and Semiconductor Association. "These projects are what will eventually help the country realise its electronics goal, since it will, for the first time, add value to the display sector in electronics manufacturing in the country. The demand for display ICs is high, and establishing this project will help India attract a full-scale display fab," he added.

priyanka.sharma@livemint.com

For an extended version of the story go to livemint.com

INDUSTRY STORY - Cabinet Approval For HCL-Foxconn OSAT Joint Venture a Strategic Milestone

ELECTRONICS

Date	14th May
Publication	ET Now
Link	https://www.youtube.com/watch?v=mxCrttiaCz0

INDUSTRY STORY -

PRINT

Date	May
Publication	Fortune India
Quote By	Ashok Chandak

IN

IN 1972, just four years after it was founded, U.S.-headquartered Intel made a defining move. The company selected Penang, Malaysia, to set up its first offshore manufacturing facility—a modest plant to package and assemble semiconductor components. By 1975, this plant was a key link in Intel's global manufacturing chain. Intel's Penang gambit was a response to Malaysia's Free Trade Zone Act of 1971, which sought to turn Penang into an export-oriented industrial zone by offering tax holidays, tariff exemptions, streamlined regulatory processes, and with sites well linked to highways, railway systems, seaports, and an airport.

Soon after Intel, giants such as AMD (which was born a year after Intel), Hitachi, and HP entered Malaysia. By the early 1980s, 14 semiconductor firms were operating in Malaysia. In just over five decades, Malaysia's early bet on electronics has made it a part of the global semiconductor value chain. Today, it hosts nine front-end fabrication units or fabs and 38 back-end facilities, including advanced packaging and testing units. It plays a vital role in global supply as companies diversify beyond China and Taiwan.

Contrast this with India, which launched its semiconductor push in December 2021 with the India Semiconductor Mission (ISM). While India had set up Semiconductor Complex Ltd in 1983, before Taiwan or China had any fabs, and Indian talent contributed to the chip design industry, SCL was destroyed in a fire in 1989. It was rebuilt in 1998, but India lost the plot.

Till the 2021 policy, India did not have a good road map for the industry. It aims to become one of the Top 5 global semiconductor ecosystems by 2030. "India will be among the Top 5 countries for semiconductor manufacturing within the next five years," Union Minister for Electronics & Information Technology (MeitY) Ashwini Vaishnaw had said.

India is trying to do in a decade what took Malaysia 55 years to create. Can it succeed? The 2021 semiconductor policy, Semicon1.0, offered ₹76,000 crore in incentives, support for setting up fabs, and chip-testing and packaging plants, together with a design ecosystem. The stakes are high, but so is the momentum. Micron Technology is building a back-end facility in Gujarat, Tata Electronics is pursuing a fab and a Semiconductor Assembly and Test unit, and other firms are getting into chip design and ATMs or assembly, testing, and marking units.

Danish Faruqui, CEO of Fab Economics, says India is now walking the talk. "The 2025 Budget allocation for subsidies for greenfield chip manufacturing and packaging projects, $1 billion, matches Germany's Budget allocation for semiconductor subsidies in 2025," says Faruqui. Fab Economics is a U.S.-based consultancy for fabs and OSAT facilities, and also offers advisory services for semiconductor investments. OSAT or Outsourced Semiconductor Assembly and Test companies provide specialised services for packaging, assembling, and testing semiconductor devices, primarily for manufacturers who design and fabricate chips but outsource the post-fabrication steps.

In the high-volume manufacturing phase, India's

PROCESSOR POWER

$627 BILLION
SIZE OF THE GLOBAL SEMICONDUCTOR MARKET IN 2024

$1 TRILLION
EXPECTED MARKET SIZE BY 2030

$52 BILLION
SIZE OF THE SEMICONDUCTOR MARKET IN INDIA IN 2024

$103.4 BILLION
EXPECTED SIZE OF INDIA'S SEMICONDUCTOR MARKET BY 2030

INDUSTRY STORY - Cabinet Approval For HCL-Foxconn OSAT Joint Venture: A Strategic Milestone

PRINT

Date	16th May
Publication	Business Remedies
Quote By	Ashok Chandak

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

IANS
New Delhi

Business Remedies. The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent and industrial scale, industry experts said.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs. 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs. 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs, addressing a critical gap in India's display and electronics value chain," said **Ashok Chandak**, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing, core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations -aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted. Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

Date	16th May
Publication	Dainik Bhor
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी

नई दिल्ली (एजेन्सी)। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बडे इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है-जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विजन के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	16th May
Publication	The Public Side
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

दी पब्लिक साइड

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	16th May
Publication	Dainik Badti Duniya
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

बढ़ती दुनिया

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	16th May
Publication	Dainik Dhola Maru
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्टक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	16th May
Publication	Dainik Taj Bharti
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्टक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	16th May
Publication	Deccan Chronicle
Quote By	Ashok Chandak

India to drop tariffs on US imports, says Trump

US President does not want Apple to set up its plants in India

SANGEETHA G.
CHENNAI, MAY 15

The US President Donald Trump has said that India has offered to drop all the tariffs on goods imported from his country, while the Indian side claims that it could be 90 per cent of goods, excluding some agricultural products and automobiles.

Trump also does not want Apple to set up its plants in India, though the industry believes Apple could never move all its production to the US.

The Indian government has offered us a deal where basically they are willing to literally charge us no tariff, Trump said at an event in Doha referring to US-India trade talks.

According to the trade, India has conceded to only 90 per cent of the US goods under zero per cent tariff.

"India could offer to make 90 per cent of US exports tariff-free from day one, using a "zero-for-zero" approach — cutting tariffs on all goods except autos and agriculture," said GTRI.

India has already lowered tariffs on Bourbon whiskey, motorcycles and a few wines. "In the case of cars, India will concede to buying vehicles under a certain cost, insurance and freight value threshold. The duties of these cars will be brought down significantly. India may not open up the automobile sector fully for American cars," said Ajay Sahai, director general, FIEO.

India may also not be buying the US dairy products as there are issues related to non-vegetarian feed given to American cows, he said.

The list of products that would be increasingly bought from the US includes petroleum from shale gas, petrochemicals, polymer, defence equipment, aircrafts and high-tech chips.

Trump also said that he has asked Apple CEO Tim Cook not to build production units in India.

"I said, 'Tim, we are treating you really good, we put up with all the plants you built in China for years. We are not interested in you building in India. India can take care of themselves", he said.

Amidst tariff war with China, Apple had recently announced that it would source the majority of its US iPhone supply from India by the end of next year. However, with China getting into talks with the US, it needs to be seen how much of the production will be moved into India.

"It is too early to predict whether Apple will move a large part of China production to India. Trump has been making statements and retracting them. While Apple may move some production to the US," said Ashok Chandak, president of India Electronics and Semiconductor Association.

Date	15th May
Publication	Mint
Quote By	Ashok Chandak

HCL-Foxconn display chip unit gets govt nod

₹3,700 cr project India's first display chip testing & manufacturing facility

Priyanka Sharma & Shouvik Das
NEW DELHI

India's display manufacturing industry received a boost on Wednesday when the Union cabinet approved the India Semiconductor Mission's (ISM) fourth chip-testing facility and the fifth semiconductor project overall.

The ₹3,700-crore (around $433 million) project, first floated in January 2024, is an outsourced semiconductor assembly and testing (Osat) facility being developed by IT services firm HCL Technologies Ltd in partnership with Taiwanese contract manufacturer Hon Hai Precision Industry Co. Ltd, better known as Foxconn.

However, the HCL-Foxconn joint venture is the first "advanced manufacturing Osat" in the country, catering specifically to displays, making it the first chip-testing project of its kind. It will help the country localise the manufacturing of displays used in mobile phones and laptops, a senior official with direct knowledge of the matter told *Mint* seeking anonymity. The unit, expected to be operational by 2027, will aim to produce 36 million chips a month by processing 20,000 semiconductor wafers.

The fifth OSAT facility in India comes as the semiconductor sector awaits cabinet approval for the second tranche of ISM incentives of up to $20 billion, aimed at supporting a $500-billion electronics economy over the next five years.

Mint reported in September that incentives may focus more on chip and display fabs than on Osat projects. However, the HCL-Foxconn Osat is in line with the overall strategy of the ISM second phase, said industry experts.

While chip-testing plants are typically of low margin and value, "the ideal strategy to set up Osats in India would either be to partner with a world-class chip and electronics brand that has existing clients and can draw business to the country, or for new forms of technology that will contribute to increasing value addition in new product categories," Jasbir Singh Gujral, managing director of electronics manufacturing firm Syrma SGS Technology Ltd, told *Mint*. It will be the first unit to help India localise display manufacturing.

HCL-Foxconn's facility under ISM scheme is likely to be operational by 2027. MINT

STACKING THE CHIPS

IT is India's 4th Osat project and 5th semiconductor unit with a focus on localising chip manufacturing.

THE plant will make complex display driver ICs and higher per-chip value than general-purpose ICs.

HCL, Foxconn team up to bring global clients and tech—a model key to Osat success in India.

This, though, is not the same as a display fabrication plant, which is responsible for the end-to-end manufacturing of the semiconductor components of a display. It is what generates the second-highest percentage of domestic value for products such as smartphones and laptops (apart from the primary processor itself).

But, according to stakeholders, it is also highly complex and costly to establish. "Besides, the HCL-Foxconn project will produce high-value display driver integrated circuits (DDICs). They are far more complex devices than general-purpose ICs that the likes of Tata Electronics Osat will produce, which will deliver higher per-chip dollar value," said Ashok Chandak, president of India Electronics and Semiconductor Association. "These projects are what will eventually help the country realise its electronics goal, since it will, for the first time, add value to the display sector in electronics manufacturing in the country. The demand for display ICs is high, and establishing this project will help India attract a full-scale display fab," he added.

priyanka.sharma@livemint.com

For an extended version of the story go to livemint.com

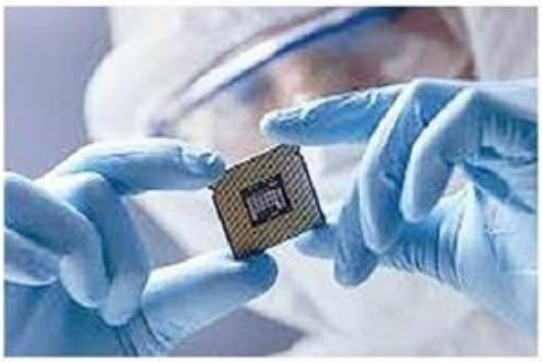
Date	15th May
Publication	Bizz Buz
Quote By	Ashok Chandak

India coming of age in semicon space

HCL-Foxconn chip plant reflects India's growing maturity

ADDING PROGRESSION

- Approved establishment of semiconductor unit in UP
- Marks a strategic milestone in India's semiconductor journey
- Addressing a critical gap in India's display, electronics value chain
- Aligning with the vision of 'Make in India' & 'Make for the World'
- The design output capacity is 36 million units per month



NEW DELHI

THE Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing -- with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs -- addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations —aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

Date	15th May
Publication	The Hindu
Quote By	Ashok Chandak

Cabinet approves ₹3,700 crore display chip-making unit in U.P.

The Hindu Bureau
NEW DELHI

The Union Cabinet on Wednesday approved a display driver chip manufacturing unit in Jewar, Uttar Pradesh, Minister of Electronics and Information Technology Ashwini Vaishnaw announced.

The unit, which will attract investments worth ₹3,700 crore according to a government statement, will be a joint venture by Indian firm HCL and Taiwanese electronics manufacturing giant Foxconn.

This semiconductor unit is the sixth to be supported under the ₹76,000 crore first phase of the India Semiconductor Mission (ISM). The unit will churn out 36 million chips a month from 20,000 wafers, Mr. Vaishnaw said.

Display panel plant will also come to India, says Vaishnaw.

"What we understand is that once this unit is there, the display panel plant will also come to India," Mr. Vaishnaw said. "This will more or less meet about 40% of India's capacity." Chips from this unit will go into laptops, PCs, phones and automobiles.

First chip plant

This is the first semiconductor plant in Uttar Pradesh, Mr. Vaishnaw said adding firms choose the States and build units themselves, calling Jewar an "up and coming industrial area".

The unit addresses "a critical gap in India's display and electronics value chain," said Ashok Chandak, president of the India Electronics and Semiconductor Association.

Date	15th May
Publication	The Telegraph
Quote By	Ashok Chandak

Foxconn, HCL team up for chip unit

PINAK GHOSH

Calcutta: Taiwanese electronics major Foxconn will take another shot at India's growing semiconductor space, this time partnering HCL to set up a display drivers chip plant in India at an investment of ₹3,700 crore.

The Union cabinet on Wednesday approved a joint venture plant between HCL and Foxconn that will be built near Jewar airport under the Yamuna Expressway Industrial Development Authority (YEIDA) in Uttar Pradesh. The plant will manufacture display driver chips for mobile phones, laptops, automobiles, PCs and other devices with displays.

The plant is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It is expected to start production in 2027.

Back in 2022, Foxconn had partnered Vedanta with plans to invest $19.5 billion to set up semiconductor fabs in India and Gujarat was selected as the final location. However, by 2023, the plan was dropped with both sides deciding to end the joint venture.

The plant will get the benefit of the incentives that are part of the India Semiconductor Mission, which offers fiscal incentives of up to 50 per cent of the project cost across different categories.

Growing ecosystem

Union minister for electronics and information technology Ashwini Vaishnaw said that the semiconductor industry is gradually shaping up in the country, with the Centre approving its sixth unit under the India Semiconductor Mission.

"This plant will make display driver chips, and this is a big requirement because electronics manufacturing is growing at a fast pace in the country," Vaishnaw said, adding that the government is also focusing on the development of the entire semiconductor ecosystem.

Applied Materials and Lam Research are two of the largest equipment manufacturers that already have a presence in India. Merck, Linde, Air Liquide, Inox and many other gas and chemical suppliers are gearing up to support the growth of the semiconductor industry.

Among the previous five projects that the government has approved under the Mission are Micron's unit in Gujarat, Tata Electronics' semiconductor fab unit in Gujarat and an assembly and assembly, testing, marketing and packaging (ATMP) unit in Assam, CG Power's ATMP unit in Gujarat and Kaynes Semicon's unit in Gujarat. These five together have a cumulative investment of ₹1,52,000 crore.

"The project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs (integrated chips) — addressing a critical gap in India's display and electronics value chain. It reflects India's growing maturity in semiconductor manufacturing with trusted partners, strategic intent and industrial scale," said Ashok Chandak, president of IESA and SEMI India.

Road ahead

Foxconn's proposed investment in India comes at a time it has downgraded its full-year outlook on Wednesday. The company, which is Apple's top iPhone assembler and Nvidia's AI server maker, has ridden the crest of the wave for artificial intelligence demand, but is also vulnerable to changes in US trade and tariff policy given its large manufacturing footprint in China and Mexico.

Foxconn chairman Young Liu said during an earnings call that US tariffs will bring more challenges, and his outlook for the full year was more cautious than earlier after the company predicted significant growth for 2025 compared with a previous outlook of strong growth.

While Washington and Beijing have agreed to slash tariffs for at least 90 days, the cheer over the temporary truce was tempered by caution, given that a more permanent trade deal needs to be struck, while higher tariffs overall could still weigh on the global economy.

Apple, which sources parts from Foxconn, had earlier indicated that it would be sourcing the majority of its phones sold in the US from India.

SECOND SHOT

- Foxconn teams up with HCL to set up a display drivers chip plant in UP
- Sixth project under India Semiconductor Mission at an investment of ₹3,700 crore
- An earlier venture between Foxconn and Vedanta did not take off

- Semiconductor ecosystem rapidly growing in India, drawing global investments
- Foxconn's India investment is amid a cautious outlook for 2025 driven by US tariff concerns

Date	15th May
Publication	Business Remedies
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

बिज़नेस रेमेडीज/नई दिल्ली

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा।

यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विजन के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बडा वैल्यू ऐडिशन कर सकती है।

Date	15th May
Publication	Dainik Adhikar
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

दैनिक अधिकार/ नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	15th May
Publication	Dainik News Jyoti
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

न्यूज ज्योति संवाददाता

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विज़न के मुताबिक है।

Date	14th May
Publication	Business Standard
Quote By	Ashok Chandak

Centre gives nod to HCL-Foxconn chip unit

AASHISH ARYAN
New Delhi, 14 May

The Union Cabinet on Wednesday approved the ₹3,706 crore HCL Group-Foxconn joint venture chip assembly unit in Uttar Pradesh's Jewar, Union Electronics and Information Technology Minister Ashwini Vaishnaw said.

The outsourced assembly and testing (OSAT) unit, which is expected to employ 2,000 people, will assemble up to 20,000 wafers per month with a design output capacity of 36 million units per month, the minister added.

"This plant will manufacture display driver chips for mobiles, laptops, personal computers, automobiles, and other electronic devices that need a display unit. This was a requirement for India as electronic manufacturing has risen multifold in recent years. The display driver chip is one of the key components in the ecosystem," Vaishnaw said, adding that the plant will use wafer-level technology to assemble chips.

THE ₹3,706 CRORE UNIT WILL BE SET UP IN JEWAR AND IS EXPECTED TO EMPLOY 2,000 PEOPLE

This is the sixth project that has been approved by the Centre under the India Semiconductor Mission (ISM).

The ₹76,000 crore ISM incentive plan, which aimed to kickstart semiconductor chip manufacturing and packaging in the country, has been successful, and has seen six applications approved.

Five of these ISM-approved projects are chip packaging units while Tata Electronics is the sole chip fabrication unit so far. The Tata Group's Dholera semiconductor unit is the sole chip fabrication facility in India, which was approved by the central government on February 29 last year under the ISM.

The plant is expected to start operations by 2027 and may employ nearly 2,000 people. The Dholera chip fabrication unit is coming up at a cost of over ₹91,000 crore.

"With an investment of ₹3,700 crore, the project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs — addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, president of the semiconductor policy advisory bodies, India Electronics and Semiconductor Association and SEMI India.

Date	14th May
Publication	Political & Business Daily
Quote By	Ashok Chandak

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

NEW DELHI, MAY 14

THE Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing -- with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs -- addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations — aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.-IANS

INDUSTRY STORY - Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

PRINT (JAIPUR)

Date	16th May
Publication	Dainik Bhor
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी

नई दिल्ली (एजेन्सी)। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बडे इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है-जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विजन के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	16th May
Publication	Business Remedies
Quote By	Ashok Chandak

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

IANS
New Delhi

Business Remedies. The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent and industrial scale, industry experts said.

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"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted. Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

Date	16th May
Publication	Dainik Dhola Maru
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्टक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	16th May
Publication	Dainik Taj Bharti
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

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दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	16th May
Publication	Bureau Sandesh
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

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Date	16th May
Publication	Saccha Sagar
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्टक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है ।

Date	16th May
Publication	Public Police Politics
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्टक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	15th May
Publication	Dainik Badti Duniya
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

बढ़ती दुनिया

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	15th May
Publication	The Public Side
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

दी पब्लिक साइड

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

Date	15th May
Publication	Uday Today
Quote By	Ashok Chandak

एचसीएल.फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

जयपुर,(उदय टुडे)। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल.फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3ए/00 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारोंए रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है . जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुपए अपनी मजबूत प्रौद्योगिकी सेवाओंए इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथए स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है।यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम ष्मेक इन इंडियाए मेक फॉर द वर्ल्डष् विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइलए लैपटॉपए कंज़्यूमर गुड्सए ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	15th May
Publication	Business Remedies
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

बिज़नेस रेमेडीज/नई दिल्ली

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर ऊन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।

यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा।

यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विजन के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बडा वैल्यू ऐडिशन कर सकती है।

Date	15th May
Publication	Dainik News Jyoti
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

न्यूज ज्योति संवाददाता

नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है - जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है। यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विज़न के मुताबिक है।

Date	15th May
Publication	Dainik Adhikar
Quote By	Ashok Chandak

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

दैनिक अधिकार/ नई दिल्ली। आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी।यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है।

INDUSTRY STORY - Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

PRINT (AHMEDABAD)

Date	16th May
Publication	Divya Gujarat
Quote By	Ashok Chandak

HCL-ફોક્સકોન OSAT સંયુક્ત સાહસને કેબિનેટ મંજૂરી મળી: ભારતના સેમિકન્ડક્ટર પેકેજિંગ નેતૃત્વ માટે માર્ગ મોકળો

HCL-Foxconn OSAT સંયુક્ત સાહસને મંત્રીમંડળની મંજૂરી ભારતની સેમિકન્ડક્ટર યાત્રામાં એક વ્યૂહાત્મક સીમાચિહ્નરૂપ છે,'' **"Rs.3,700** કરોડના રોકાણ સાથે, આ પ્રોજેક્ટ ખાસ કરીને ડિસ્પ્લે ડ્રાઇવર **IC** માટે મોટા પાયે અદ્યતન પેકેજિંગ અને પરીક્ષણ ક્ષમતાઓ લાવે છે - જે ભારતની ડિસ્પ્લે અને ઇલેક્ટ્રોનિક્સ મૂલ્ય શૃંખલામાં એક મહત્વપૂર્ણ અંતરને સંબોધે છે.

આ ફક્ત માળખાગત સુવિધાઓ બનાવવા વિશે નથી - તે વિશ્વસનીય ભાગીદારો, વ્યૂહાત્મક ઉદ્દેશ્ય અને ઔદ્યોગિક સ્કેલ સાથે સેમિકન્ડક્ટર ઉત્પાદનમાં ભારતની વધતી જતી પરિપક્વતાને પ્રતિબિંબિત કરે છે.'' **IESA** અને **SEMI** ઇન્ડિયાના પ્રમુખ અશોક ચાંડકે ટિપ્પણી કરી.

વિશ્વના સૌથી મોટા ઇલેક્ટ્રોનિક્સ ઉત્પાદકોમાંના એક, ફોક્સકોન, ચિપ પેકેજિંગ અને પરીક્ષણમાં વિશ્વ કક્ષાની કુશળતા લાવે છે - ડાઉનસ્ટ્રીમ સેમિકન્ડક્ટર સપ્લાય ચેઇનમાં મુખ્ય. **HCL** ગ્રુપ, તેની મજબૂત ટેકનોલોજી સેવાઓ, એન્જિનિયરિંગ શક્તિ અને વૈશ્વિક સંબંધો સાથે, સ્થાનિક અમલીકરણ ક્ષમતા અને પ્રતિભાની ઍક્સેસ ઉમેરે છે. ચાંડકે ઉમેર્યું : "સાથે મળીને, આ સંયુક્ત સાહસ ભારતને સેમિકન્ડક્ટર **OSAT** કામગીરી માટે પસંદગીના વૈશ્વિક કેન્દ્ર તરીકે ઉભરી આવવા માટે પાયો નાખે છે - જે ખરેખર કેન્દ્ર અને રાજ્યોના મહાન સમર્થન સાથે 'મેક ઈન ઈન્ડિયા, મેક ફોર ધ વર્લ્ડ' ના વિઝન સાથે સંરેખિત છે અને આ પ્રોજેક્ટ સીમાચિહ્નરૂપ બની શકે છે કારણ કે તે મોબાઈલ, લેપટોપ, ગ્રાહક, ઓટોમોટિવ, વગેરે માટે ભારતના ઈલેક્ટ્રોનિક્સ ઉત્પાદનમાં મુખ્ય મૂલ્યવર્ધન કરી શકે છે."

Date	15th May
Publication	Gujarat Pranam
Quote By	Ashok Chandak

HCL-ફોક્સકોન OSAT સંયુક્ત સાહસને કેબિનેટ મંજૂરી મળી: ભારતના સેમિકન્ડક્ટર પેકેજિંગ નેતૃત્વ માટે માર્ગ મોકળો

HCL-Foxconn OSAT સંયુક્ત સાહસને મંત્રીમંડળની મંજૂરી ભારતની સેમિકન્ડક્ટર યાત્રામાં એક વ્યૂહાત્મક સીમાચિહ્નરૂપ છે,'' ''૩,૭૦૦ કરોડના રોકાણ સાથે, આ પ્રોજેક્ટ ખાસ કરીને ડિસ્પ્લે ડ્રાઇવર **IC** માટે મોટા પાયે અદ્યતન પેકેજિંગ અને પરીક્ષણ ક્ષમતાઓ લાવે છે - જે ભારતની ડિસ્પ્લે અને ઇલેક્ટ્રોનિક્સ મૂલ્ય શૃંખલામાં એક મહત્વપૂર્ણ અંતરને સંબોધે છે.

આ ફક્ત માળખાગત સુવિધાઓ બનાવવા વિશે નથી - તે વિશ્વસનીય ભાગીદારો, વ્યૂહાત્મક ઉદ્દેશ્ય અને ઔદ્યોગિક સ્કેલ સાથે સેમિકન્ડક્ટર ઉત્પાદનમાં ભારતની વધતી જતી પરિપક્વતાને પ્રતિબિંબિત કરે છે.'' **IESA** અને **SEMI** ઇન્ડિયાના પ્રમુખ અશોક ચાંડકે ટિપ્પણી કરી.

વિશ્વના સૌથી મોટા ઇલેક્ટ્રોનિક્સ ઉત્પાદકોમાંના એક, ફોક્સકોન, ચિપ પેકેજિંગ અને પરીક્ષણમાં વિશ્વ કક્ષાની કુશળતા લાવે છે - ડાઉનસ્ટ્રીમ સેમિકન્ડક્ટર સપ્લાય ચેઇનમાં મુખ્ય. ૐઝ્ર ગ્રુપ, તેની મજબૂત ટેકનોલોજી સેવાઓ, એન્જિનિયરિંગ શક્તિ અને વૈશ્વિક સંબંધો સાથે, સ્થાનિક અમલીકરણ ક્ષમતા અને પ્રતિભાની ઍક્સેસ ઉમેરે છે. ચાંડકે ઉમેર્યું : "સાથે મળીને, આ સંયુક્ત સાહસ ભારતને સેમિકન્ડક્ટર **OSAT** કામગીરી માટે પસંદગીના વૈશ્વિક કેન્દ્ર તરીકે ઉભરી આવવા માટે પાયો નાખે છે - જે ખરેખર કેન્દ્ર અને રાજ્યોના મહાન સમર્થન સાથે 'મેક ઈન ઈન્ડિયા, મેક ફોર ધ વર્લ્ડ' ના વિઝન સાથે સંરેખિત છે અને આ પ્રોજેક્ટ સીમાચિહ્નરૂપ બની શકે છે કારણ કે તે મોબાઈલ, લેપટોપ, ગ્રાહક, ઓટોમોટિવ, વગેરે માટે ભારતના ઇલેક્ટ્રોનિક્સ ઉત્પાદનમાં મુખ્ય મૂલ્યવર્ધન કરી શકે છે."

INDUSTRY STORY - Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

PRINT (CHENNAI)

Date	19th May
Publication	Dina Kathri
Quote By	Ashok Chandak

ஹெச்சிஎல்–ஃபாக்ஸ்கான் ஓஎஸ்ஏடி தொழில் கூட்டு புரிந்துணர்வுக்கு மத்திய அமைச்சரவை ஒப்புதல் அளித்தது உத்திசார் அடிப்படையில் இந்தியாவின் செமி கண்டக்டர் உற்பத்தி பயணத்தில் ஒரு குறிப்பிடத்தக்க மைல்கல் முயற்சியாகும்

சென்னை, மே 19: ஹெச்சிஎல்-ஃபாக்ஸ்கான் ஓஎஸ் ஏடி தொழில் கூட்டு புரிந்துணர்வுக்கு மத்திய அமைச்சரவை ஒப்புதல் அளித்தது உத்திசார் அடிப்படையில் இந்தியாவின் செமி கண்டக்டர் உற்பத்தி பயணத்தில் ஒரு குறிப்பிடத்தக்க மைல்கல் முயற்சியாகும். ரூ. 3,700 கோடி முதலீட்டிலான இந்தத்திட்டம் மூலம் பெரிய அளவிலான மேம்பட்ட பேக்கேஜிங் மற்றும் சோதித்தறியும் நுட்பம் குறிப்பாக டிஸ்பிளே டிரைவர் இன்டகரேட்டட் சர்கியூட் (ஐசி), அதாவது டிஸ்பிளே மற்றும் எலெக்ட்ரானிக் தொழில்நுட்ப சங்கிலியில் நிலவும் இடைவெளியைப் போக்க உதவும்.

''இது உள்கட்டமைப்பை உருவாக்குவதுமட்டுமல்ல, செமி கண்டக்டர் எனப்படும் அரை கடத்தி உற்பத்தியில் இந்தியா எட்டியுள்ள வளர்ச்சியில் முதிர்ச்சியை பிரதிபலிக்கிறது. அதற்கேற்ப நம்பகமான கூட்டாளிகள், உத்திசார் நோக்கம் மற்றும் இத்துறை வளர்ச்சியைக் காட்டுகிறது,'' என்று ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா கூட்டமைப்பின் தலைவர் அசோக் சந்தக் குறிப்பிட்டுள்ளார்.

உலக அளவில் மின்னணு உற்பத்தியில் மிகப் பெரிய நிறுவனமாக ஃபாக்ஸ்கான் திகழ்கிறது. இந்நிறுவனம் சிப்- பேக்கேஜிங் மற்றும் சோதித்தறிவதில் உலக தரத்திலான நிபுணத்துவத்தைக்

கொண்டுள்ளது. இதுதான் செமி-கண்டக்டர் விநியோக சங்கிலியின் பிரதான தேவையாகும். ஹெச்சிஎல் குழுமமானது தொழில்நுட்ப சேவை மற்றும் பொறியியல் நுட்பத் திறன் கொண்ட நிறுவனமாகும். இந்நிறுவனத்துக்கு சர்வதேச அளவில் வலுவான தொடர்புகள் உள்ளன. அத்துடன் உள்ளூரில் திறமையான வர்களைக் கொண்டு பொருள்களைத் தயாரிப்பதில் இந்நிறுவனம் சிறப்பாகச் செயல்படும்.

''இவ்விரு நிறுவனங்களும் கூட்டாக இணைவது செமி கண்டக்டர் துறையில் வலுவான தளமாக இந்தியா உருவாகி வருவதற்கு அடித்தளமாக அமையும். இது ஓஎஸ்ஏடி செயல்பாடுகளுக்கு தளமாக விளக்கும். இது ''மேக் இன் இந்தியா'' திட்டத்தின் இலக்கை எட்டுவதோடு உலக அளவிலான பெரும் ஆதரவைப் பெறும் மையமாகத் திகழும். இது மத்திய மற்றும் மாநிலங்களுக்கு மிகச் சிறந்த திட்டமாகும். அத்துடன் மொபைல், லேப்டாப், நுகர்வோர், ஆட்டோமோடிவ் உள்ளிட்ட மின்னணு துறையில் இந்தியா மிகச் சிறந்த மதிப்புக் கூட்டல் சேவையை அளிப்பதற்கு இந்த வரலாற்று சிறப்பு வாய்ந்த திட்டம் உதவும்,'' என்று அசோக் சந்தக் மேலும் கூறினார்.

Date	19th May
Publication	Tamil Sudar
Quote By	Ashok Chandak

செமி கண்டக்டர் உற்பத்தியில் இந்தியாவின் வளர்ந்து வரும் முதிர்ச்சியை பிரதிபலிக்கிறது ஹெச்சிஎல் ஃபாக்ஸ்கான் ஆலை

சென்னை, மே 18–

ஹெச்சிஎல் ஃபாக்ஸ்கான் ஓஎஸ்ஏடி தொழில் கூட்டு புரிந்துணர்வு க்கு மத்திய அமைச்சரவை ஒப்புதல் அளித்தது உத்திசார் அடிப்படையில் இந்தியாவின் செமி கண்டக்டர் உற்பத்தி பயணத்தில் ஒரு குறிப்பிடத்தக்க மைல்கல் முயற்சியாகும். ரூ. 3,700 கோடி முதலீட்டிலான இந்தத்திட்டம் மூலம் பெரிய அளவிலான மேம்பட்ட பேக்கேஜிங் மற்றும் சோதித்தறியும் நுட்பம் குறிப்பாக டிஸ்பிளே டிரைவர் இன்டகரேட்டட் சர்கியூட் (ஐசி), அதாவது டிஸ்பிளே மற்றும் எலெக்ட்ரானிக் தொழில்நுட்ப சங்கிலியில் நிலவும் இடைவெளியைப் போக்க உதவும்.``இது உள்கட்டமைப்பை உருவாக்குவதுமட்டுமல்ல, செமி கண்டக்டர் எனப்படும் அரை கடத்திஉற்பத்தியில் இந்தியாஎட்டியுள்ளவளர்ச்சியில் முதிர்ச்சியை பிரதிபலிக்கிறது. அதற்கேற்பநம்பகமான கூட்டாளிகள், உத்திசார் நோக்கம் மற்றும் இத்துறை வளர்ச்சியைக் காட்டுகிறது,'' என்று ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா கூட்டமைப்பின் தலைவர் அசோக் சந்தக் குறிப்பிட்டுள்ளார். உலக அளவில் மின்னணு உற்பத்தியில் மிகப் பெரியநிறுவனமாக ஃபாக்ஸ்கான் திகழ்கிறது. இந்நிறுவனம் சிப் பேக்கேஜிங் மற்றும் சோதித்தறிவதில் உலக தரத்திலான நிபுணத்துவத்தைக் கொண்டுள்ளது. இதுதான் செமிகண்டக்டர் விநியோக சங்கிலியின் பிரதான தேவையாகும். ஹெச்சிஎல் குழுமமானது தொழில்நுட்ப சேவை மற்றும் பொறி யியல் நுட்பத் திறன் கொண்ட நிறுவனமாகும். இது ஓஎஸ்ஏடி செயல்பாடுகளுக்கு தளமாக விளக்கும். இது ``மேக் இன் இந்தியா'' திட்டத்தின் இலக்கைஎட்டுவதோடு உலக அளவிலான பெரும் ஆதரவைப் பெறும் மையமாகத் திகழும். இது மத்திய மற்றும் மாநிலங்களுக்கு மிகச் சிறந்த திட்டமாகும். அத்துடன் மொபைல், லேப்டாப், நுகர்வோர், ஆட்டோமோடிவ் உள்ளிட்ட மின்னணு துறையில் இந்தியா மிகச் சிறந்த மதிப்புக் கூட்டல் சேவையை அளிப்பதற்கு இந்த வரலாற்று சிறப்பு வாய்ந்த திட்டம் உதவும்,'' என்று அசோக் சந்தக் மேலும் கூறினார்.

Date	19th May
Publication	Velli Ethal
Quote By	Ashok Chandak

செமி கண்டக்டர் உற்பத்தியில் இந்தியாவின் வளர்ந்து வரும் முதிர்ச்சியை பிரதிபலிக்கிறது ஹெச்சிஎல் ஃபாக்ஸ்கான் ஆலை

சென்னை, மே 19: ஹெச்சிஎல்–ஃபாக்ஸ்கான் ஓஎஸ்ஏடி தொழில் கூட்டு புரிந்துணர்வுக்கு மத்திய அமைச்சரவை ஒப்புதல் அளித்தது உத்திசார் அடிப்படையில் இந்தியாவின் செமி கண்டக்டர் உற்பத்தி பயணத்தில் ஒரு குறிப்பிடத்தக்க மைல்கல் முயற்சியாகும். ரூ. 3,700 கோடி முதலீட்டிலான இந்தத்திட்டம் மூலம் பெரிய அளவிலான மேம்பட்ட பேக்கேஜிங் மற்றும் சோதித்தறியும் நுட்பம் குறிப்பாக டிஸ்பிளே டிரைவர் இன்டகரேட்டட் சர்கியூட் (ஐசி), அதாவது டிஸ்பிளே மற்றும் எலெக்ட்ரானிக் தொழில்நுட்ப சங்கிலியில் நிலவும் இடைவெளியைப் போக்க உதவும்.

``இது உள்கட்டமைப்பை உருவாக்குவதுமட்டுமல்ல, செமி கண்டக்டர் எனப்படும் அரை கடத்தி உற்பத்தியில் இந்தியா எட்டியுள்ள வளர்ச்சியில் முதிர்ச்சியை பிரதிபலிக்கிறது. அதற்கேற்ப நம்பகமான கூட்டாளிகள், உத்திசார் நோக்கம் மற்றும் இத்துறை வளர்ச்சியைக் காட்டுகிறது,'' என்று ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா கூட்டமைப்பின் தலைவர் அசோக் சந்தக் குறிப்பிட்டுள்ளார்.

உலக அளவில் மின்னணு உற்பத்தியில் மிகப் பெரிய நிறுவனமாக ஃபாக்ஸ்கான் திகழ்கிறது. இந்நிறுவனம் சிப்– பேக்கேஜிங் மற்றும் சோதித்தறிவதில் உலக தரத்திலான நிபுணத்துவத்தைக் கொண்டுள்ளது. இதுதான் செமி–கண்டக்டர் விநியோக சங்கிலியின் பிரதான தேவையாகும். ஹெச்சிஎல் குழுமமானது தொழில்நுட்ப சேவை மற்றும் பொறியியல் நுட்பத் திறன் கொண்ட நிறுவனமாகும். இந்நிறுவனத்துக்கு சர்வதேச அளவில் வலுவான தொடர்புகள் உள்ளன.அத்துடன் உள்ளூரில் திறமையானவர்களைக் கொண்டு பொருள் களைத் தயாரிப்பதில் இந்நிறுவனம் சிறப்பாகச் செயல்படும்.

``இவ்விரு நிறுவனங்களும் கூட்டாக இணைவது செமி கண்டக்டர் துறையில் வலுவான தளமாக இந்தியா உருவாகி வருவதற்கு அடித்தளமாக அமையும். இது ஓஎஸ்ஏடி செயல்பாடுகளுக்கு தளமாக விளக்கும். இது ``மேக் இன் இந்தியா'' திட்டத்தின் இலக்கை எட்டுவதோடு உலக அளவிலான பெரும் ஆதரவைப் பெறும் மையமாகத் திகழும். இது மத்திய மற்றும் மாநிலங்களுக்கு மிகச் சிறந்த திட்டமாகும். அத்துடன் மொபைல், லேப்டாப், நுகர்வோர், ஆட்டோமோடிவ் உள்ளிட்ட மின்னணு துறையில் இந்தியா மிகச் சிறந்த மதிப்புக் கூட்டல் சேவையை அளிப்பதற்கு இந்த வரலாற்று சிறப்பு வாய்ந்த திட்டம் உதவும்,'' என்று அசோக் சந்தக் மேலும் கூறினார்.

Date	18th May
Publication	Dina Kural
Quote By	Ashok Chandak

செமி கண்டக்டர் உற்பத்தியில் இந்தியாவின் வளர்ந்து வரும் முதிர்ச்சியை பிரதிபலிக்கிறது ஹெச்சிஎல் ஃபாக்ஸ்கான் ஆலை

சென்னை, மே, 18: ஹெச்சிஎல்-ஃபாக்ஸ்கான் ஓஎஸ்ஏடி தொழில் கூட்டு புரிந்துணர்வுக்கு மத்திய அமைச்சரவை ஒப்புதல் அளித்தது உத்திசார் அடிப்படையில் இந்தியாவின் செமி கண்டக்டர் உற்பத்தி பயணத்தில் ஒரு குறிப்பிடத்தக்க மைல்கல் முயற்சியாகும். ரூ. 3,700 கோடி முதலீட்டிலான இந்தத்திட்டம் மூலம் பெரிய அளவிலான மேம்பட்ட பேக்கேஜிங் மற்றும் சோதித்தறியும் நுட்பம் குறிப்பாக டிஸ்பிளே டிரைவர் இன்டகரேட்டட் சர்கியூட் (ஐசி), அதாவது டிஸ்பிளே மற்றும் எலெக்ட்ரானிக் தொழில்நுட்ப சங்கிலியில் நிலவும் இடைவெளியைப் போக்க உதவும்.

"இது உள்கட்டமைப்பை உருவாக்குவதுமட்டுமல்ல, செமி கண்டக்டர் எனப்படும் அரை கடத்தி உற்பத்தியில் இந்தியா எட்டியுள்ள வளர்ச்சியில் முதிர்ச்சியை பிரதிபலிக்கிறது. அதற்கேற்ப நம்பகமான கூட்டாளிகள், உத்திசார் நோக்கம் மற்றும் இத்துறை வளர்ச்சியைக் காட்டுகிறது," என்று ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா கூட்டமைப்பின் தலைவர் அசோக் சந்தக் குறிப்பிட்டுள்ளார்.

உலக அளவில் மின்னணு உற்பத்தியில் மிகப் பெரிய நிறுவனமாக ஃபாக்ஸ்கான் திகழ்கிறது. இந்நிறுவனம் சிப்- பேக்கேஜிங் மற்றும் சோதித்தறிவதில் உலக தரத்திலான நிபுணத்துவத்தைக் கொண்டுள்ளது. இதுதான் செமி-கண்டக்டர் விநியோக சங்கிலியின் பிரதான தேவையாகும். ஹெச்சிஎல் குழுமமானது தொழில்நுட்ப சேவை மற்றும் பொறியியல் நுட்பத் திறன் கொண்ட நிறுவனமாகும். இந்நிறுவனத்துக்கு சர்வதேச அளவில் வலுவான தொடர்புகள் உள்ளன.அத்துடன் உள்ளூரில் திறமையானவர்களைக் கொண்டு பொருள்களைத் தயாரிப்பதில் இந்நிறுவனம் சிறப்பாகச் செயல்படும்.

"இவ்விரு நிறுவனங்களும் கூட்டாக இணைவது செமி கண்டக்டர் துறையில் வலுவான தளமாக இந்தியா உருவாகி வருவதற்கு அடித்தளமாக அமையும். இது ஓஎஸ்ஏடி செயல்பாடுகளுக்கு தளமாக விளக்கும். இது "மேக் இன் இந்தியா" திட்டத்தின் இலக்கை எட்டுவதோடு உலக அளவிலான பெரும் ஆதரவைப் பெறும் மையமாகத் திகழும். இது மத்திய மற்றும் மாநிலங்களுக்கு மிகச் சிறந்த திட்டமாகும். அத்துடன் மொபைல், லேப்டாப், நுகர்வோர், ஆட்டோமோடிவ் உள்ளிட்ட மின்னணு துறையில் இந்தியா மிகச் சிறந்த மதிப்புக் கூட்டல் சேவையை அளிப்பதற்கு இந்த வரலாற்று சிறப்பு வாய்ந்த திட்டம் உதவும்," என்று அசோக் சந்தக் மேலும் கூறினார்.

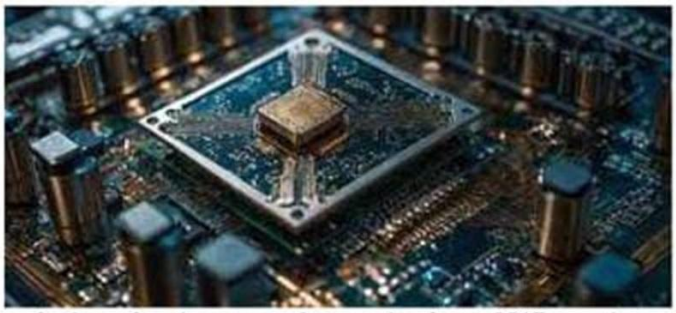
Date	17th May
Publication	News Today
Quote By	Ashok Chandak

HCL- Foxconn come together from semiconductor journey

Chennai, May 17:

The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey," "With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.

This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale." Commented Ashok Chandak, President IESA and SEMI India.



Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing—core to the downstream semiconductor supply chain. HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for Mobiles, Laptops, Consumer, Automotive, etc.'" Chandak added.

Date	17th May
Publication	Trinity Mirror
Quote By	Ashok Chandak

HCL-Foxconn JV fillip for semicon industry

Chennai, May 17:

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Date	17th May
Publication	Business Minute
Quote By	Ashok Chandak

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

CHENNAI

The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey," "With an investment of ₹3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.

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Date	17th May
Publication	Southern Mail
Quote By	Ashok Chandak

HCL-FOXCONN PLANT REFLECTS INDIA'S GROWING MATURITY IN SEMICONDUCTOR MANUFACTURING

Chennai: The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey," "With an investment of ₹3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.

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Date	17th May
Publication	Virtual Times
Quote By	Ashok Chandak

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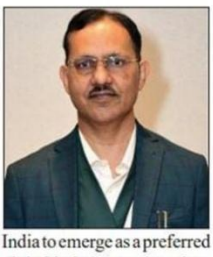

India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for Mobiles, Laptops, Consumer, Automotive, etc.'" Chandak added.

INDUSTRY STORY - Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

PRINT (GUJARAT)

Date	16th May
Publication	Divya Gujarat
Quote By	Ashok Chandak

HCL-ફોક્સકોન OSAT સંયુક્ત સાહસને કેબિનેટ મંજૂરી મળી: ભારતના સેમિકન્ડક્ટર પેકેજિંગ નેતૃત્વ માટે માર્ગ મોકળો

HCL-Foxconn OSAT સંયુક્ત સાહસને મંત્રીમંડળની મંજૂરી ભારતની સેમિકન્ડક્ટર યાત્રામાં એક વ્યૂહાત્મક સીમાચિહ્નરૂપ છે,'' **"Rs.3,700** કરોડના રોકાણ સાથે, આ પ્રોજેક્ટ ખાસ કરીને ડિસ્પ્લે ડ્રાઇવર **IC** માટે મોટા પાયે અદ્યતન પેકેજિંગ અને પરીક્ષણ ક્ષમતાઓ લાવે છે - જે ભારતની ડિસ્પ્લે અને ઇલેક્ટ્રોનિક્સ મૂલ્ય શૃંખલામાં એક મહત્વપૂર્ણ અંતરને સંબોધે છે.

આ ફક્ત માળખાગત સુવિધાઓ બનાવવા વિશે નથી - તે વિશ્વસનીય ભાગીદારો, વ્યૂહાત્મક ઉદ્દેશ્ય અને ઔદ્યોગિક સ્કેલ સાથે સેમિકન્ડક્ટર ઉત્પાદનમાં ભારતની વધતી જતી પરિપક્વતાને પ્રતિબિંબિત કરે છે.'' **IESA** અને **SEMI** ઇન્ડિયાના પ્રમુખ અશોક ચાંડકે ટિપ્પણી કરી.

વિશ્વના સૌથી મોટા ઇલેક્ટ્રોનિક્સ ઉત્પાદકોમાંના એક, ફોક્સકોન, ચિપ પેકેજિંગ અને પરીક્ષણમાં વિશ્વ કક્ષાની કુશળતા લાવે છે - ડાઉનસ્ટ્રીમ સેમિકન્ડક્ટર સપ્લાય ચેઇનમાં મુખ્ય. **HCL** ગ્રુપ, તેની મજબૂત ટેકનોલોજી સેવાઓ, એન્જિનિયરિંગ શક્તિ અને વૈશ્વિક સંબંધો સાથે, સ્થાનિક અમલીકરણ ક્ષમતા અને પ્રતિભાની ઍક્સેસ ઉમેરે છે. ચાંડકે ઉમેર્યું : "સાથે મળીને, આ સંયુક્ત સાહસ ભારતને સેમિકન્ડક્ટર **OSAT** કામગીરી માટે પસંદગીના વૈશ્વિક કેન્દ્ર તરીકે ઉભરી આવવા માટે પાયો નાખે છે - જે ખરેખર કેન્દ્ર અને રાજ્યોના મહાન સમર્થન સાથે 'મેક ઈન ઈન્ડિયા, મેક ફોર ધ વર્લ્ડ' ના વિઝન સાથે સંરેખિત છે અને આ પ્રોજેક્ટ સીમાચિહ્નરૂપ બની શકે છે કારણ કે તે મોબાઈલ, લેપટોપ, ગ્રાહક, ઓટોમોટિવ, વગેરે માટે ભારતના ઇલેક્ટ્રોનિક્સ ઉત્પાદનમાં મુખ્ય મૂલ્યવર્ધન કરી શકે છે."

Date	15th May
Publication	Sabandh Bharat
Quote By	Ashok Chandak

HCL-ફોક્સકોન OSAT સંયુક્ત સાહસને કેબિનેટ મંજૂરી મળી: ભારતના સેમિકન્ડક્ટર પેકેજિંગ નેતૃત્વ માટે માર્ગ મોકળો

HCL-Foxconn OSAT સંયુક્ત સાહસને મંત્રીમંડળની મંજૂરી ભારતની સેમિકન્ડક્ટર યાત્રામાં એક વ્યૂહાત્મક સીમાચિહ્નરૂપ છે,'' ''૩,૭૦૦ કરોડના રોકાણ સાથે, આ પ્રોજેક્ટ ખાસ કરીને ડિસ્પ્લે ડ્રાઇવર **IC** માટે મોટા પાયે અદ્યતન પેકેજિંગ અને પરીક્ષણ ક્ષમતાઓ લાવે છે - જે ભારતની ડિસ્પ્લે અને ઇલેક્ટ્રોનિક્સ મૂલ્ય શૃંખલામાં એક મહત્વપૂર્ણ અંતરને સંબોધે છે.

આ ફક્ત માળખાગત સુવિધાઓ બનાવવા વિશે નથી - તે વિશ્વસનીય ભાગીદારો, વ્યૂહાત્મક ઉદ્દેશ્ય અને ઔદ્યોગિક સ્કેલ સાથે સેમિકન્ડક્ટર ઉત્પાદનમાં ભારતની વધતી જતી પરિપક્વતાને પ્રતિબિંબિત કરે છે.'' **IESA** અને **SEMI** ઇન્ડિયાના પ્રમુખ અશોક ચાંડકે ટિપ્પણી કરી.

વિશ્વના સૌથી મોટા ઇલેક્ટ્રોનિક્સ ઉત્પાદકોમાંના એક, ફોક્સકોન, ચિપ પેકેજિંગ અને પરીક્ષણમાં વિશ્વ કક્ષાની કુશળતા લાવે છે - ડાઉનસ્ટ્રીમ સેમિકન્ડક્ટર સપ્લાય ચેઇનમાં મુખ્ય. ૐઝ્ર ગ્રુપ, તેની મજબૂત ટેકનોલોજી સેવાઓ, એન્જિનિયરિંગ શક્તિ અને વૈશ્વિક સંબંધો સાથે, સ્થાનિક અમલીકરણ ક્ષમતા અને પ્રતિભાની ઍક્સેસ ઉમેરે છે. ચાંડકે ઉમેર્યું : "સાથે મળીને, આ સંયુક્ત સાહસ ભારતને સેમિકન્ડક્ટર **OSAT** કામગીરી માટે પસંદગીના વૈશ્વિક કેન્દ્ર તરીકે ઉભરી આવવા માટે પાયો નાખે છે - જે ખરેખર કેન્દ્ર અને રાજ્યોના મહાન સમર્થન સાથે 'મેક ઈન ઈન્ડિયા, મેક ફોર ધ વર્લ્ડ' ના વિઝન સાથે સંરેખિત છે અને આ પ્રોજેક્ટ સીમાચિહ્નરૂપ બની શકે છે કારણ કે તે મોબાઈલ, લેપટોપ, ગ્રાહક, ઓટોમોટિવ, વગેરે માટે ભારતના ઇલેક્ટ્રોનિક્સ ઉત્પાદનમાં મુખ્ય મૂલ્યવર્ધન કરી શકે છે."

Date	15th May
Publication	Sabandh Bharat
Quote By	Ashok Chandak

HCL-ફોક્સકોન OSAT સંયુક્ત સાહસને કેબિનેટ મંજૂરી મળી: ભારતના સેમિકન્ડક્ટર પેકેજિંગ નેતૃત્વ માટે માર્ગ મોકળો

HCL-Foxconn OSAT સંયુક્ત સાહસને મંત્રીમંડળની મંજૂરી ભારતની સેમિકન્ડક્ટર યાત્રામાં એક વ્યૂહાત્મક સીમાચિહ્નરૂપ છે,'' ''૩,૭૦૦ કરોડના રોકાણ સાથે, આ પ્રોજેક્ટ ખાસ કરીને ડિસ્પ્લે ડ્રાઈવર **IC** માટે મોટા પાયે અદ્યતન પેકેજિંગ અને પરીક્ષણ ક્ષમતાઓ લાવે છે - જે ભારતની ડિસ્પ્લે અને ઈલેક્ટ્રોનિક્સ મૂલ્ય શૃંખલામાં એક મહત્વપૂર્ણ અંતરને સંબોધે છે.

આ ફક્ત માળખાગત સુવિધાઓ બનાવવા વિશે નથી - તે વિશ્વસનીય ભાગીદારો, વ્યૂહાત્મક ઉદ્દેશ્ય અને ઔદ્યોગિક સ્કેલ સાથે સેમિકન્ડક્ટર ઉત્પાદનમાં ભારતની વધતી જતી પરિપક્વતાને પ્રતિબિંબિત કરે છે.'' **IESA** અને **SEMI** ઈન્ડિયાના પ્રમુખ અશોક ચાંડકે ટિપ્પણી કરી.

વિશ્વના સૌથી મોટા ઈલેક્ટ્રોનિક્સ ઉત્પાદકોમાંના એક, ફોક્સકોન, ચિપ પેકેજિંગ અને પરીક્ષણમાં વિશ્વ કક્ષાની કુશળતા લાવે છે - ડાઉનસ્ટ્રીમ સેમિકન્ડક્ટર સપ્લાય ચેઇનમાં મુખ્ય. ૩૫૯-ગ્રુપ, તેની મજબૂત ટેકનોલોજી સેવાઓ, એન્જિનિયરિંગ શક્તિ અને વૈશ્વિક સંબંધો સાથે, સ્થાનિક અમલીકરણ ક્ષમતા અને પ્રતિભાની ઍક્સેસ ઉમેરે છે. ચાંડકે ઉમેર્યું: "સાથે મળીને, આ સંયુક્ત સાહસ ભારતને સેમિકન્ડક્ટર **OSAT** કામગીરી માટે પસંદગીના વૈશ્વિક કેન્દ્ર તરીકે ઉભરી આવવા માટે પાયો નાખે છે - જે ખરેખર કેન્દ્ર અને રાજ્યોના મહાન સમર્થન સાથે 'મેક ઈન ઈન્ડિયા, મેક ફોર ધ વર્લ્ડ' ના વિઝન સાથે સંરેખિત છે અને આ પ્રોજેક્ટ સીમાચિહ્નરૂપ બની શકે છે કારણ કે તે મોબાઈલ, લેપટોપ, ગ્રાહક, ઓટોમોટિવ, વગેરે માટે ભારતના ઈલેક્ટ્રોનિક્સ ઉત્પાદનમાં મુખ્ય મૂલ્યવર્ધન કરી શકે છે."

INDUSTRY STORY - Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

ONLINE

Date	15th May
Publication	IANS Business
Link	https://www.business-standard.com/industry/news/cabinet-clears-hcl-foxconn-chip-assembly-unit-under-india-semiconductor-125051401135_1.html

IANS May 14, 2025 4:46 PM

New Delhi, May 14 (IANS) The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing -- with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs -- addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations —aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

Date	15th May
Publication	The Hindu
Link	https://www.thehindu.com/incoming/cabinet-approves-3700-crore-display-chip-unit-in-uttar-pradesh/article69575226.ece

Cabinet approves ₹3,700 crore display chip unit in Uttar Pradesh

This will be the latest semiconductor project approved under the India Semiconductor Mission's first phase, and will churn out 36 million chips a month.

Updated - May 15, 2025 10:44 am IST - NEW DELHI

THE HINDU BUREAU

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The Union Cabinet on Wednesday approved a display driver chip manufacturing unit in Jewar, Uttar Pradesh, Minister of Electronics and Information Technology Ashwini Vaishnaw announced. The unit, which will attract investments of ₹3,700 crore according to a government statement, will be a joint venture by Indian firm HCL and Taiwanese electronics manufacturing giant Foxconn.

Union Information & Broadcasting Minister Ashwini Vaishnaw at the National Media Centre in New Delhi. | Photo Credit: ANI

This semiconductor unit is the sixth to be supported under the ₹76,000 crore first phase of the India Semiconductor Mission (ISM). The unit will churn out 36 million chips a month from 20,000 wafers, Mr. Vaishnaw said. "What we understand is that once this unit is there, the display panel plant will also come to India," Mr. Vaishnaw said. "This will more or less meet about 40% of India's capacity." Chips from this unit will go into laptops, PCs, phones and automobiles. Mr. Vaishnaw said.

This is the first semiconductor plant in Uttar Pradesh; Mr. Vaishnaw said that firms choose the States they build units in themselves, calling Jewar an "up and coming industrial area". The unit addresses "a critical gap in India's display and electronics value chain," said Ashok Chandak, president of the India Electronics and Semiconductor Association.

"Typically this kind of plant takes about 2 to 3 years for getting all the permits and applications and approvals," Mr. Vaishnaw said, but approvals for the previous five units under the ISM have happened in less than 120 days. "The company has already told us that commercial production will start in 2027," Mr. Vaishnaw said. "We are already in 2025, right? So that means construction has to go very fast."

The other plants are in Dholera, Gujarat by Powerchip Semiconductor Manufacturing Corporation and Tata Electronics; Sanand, Gujarat by Micron; another plant in Sanand by Kaynes; a Tata semiconductor assembly plant in Morigaon, Assam; and another assembly unit in Sanand by CG Power and Japanese technology firm Renesas.

Date	15th May
Publication	Democratic Jagat
Link	https://democraticjagat.com/news-post/9119/cabinet-approval-for-hcl-foxconn-osat-joint-venture-a-strategic-milestone#google_vignette

Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey," "With an investment of ₹3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.

This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale." Commented Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing—core to the downstream semiconductor supply chain. HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for Mobiles, Laptops, Consumer, Automotive, etc. .'" Chandak added.

Date	15th May
Publication	Entrepreneur
Link	https://www.entrepreneur.com/en-in/technology/cabinet-approval-of-hcl-foxconn-jv-a-fillip-for-semicon/491682

Cabinet Approval of HCL-Foxconn JV a Fillip for Semicon Manufacturing in India

India's semiconductor market is expected to grow from USD 52 billion in 2024 to USD 103.4 billion by 2030, according to a report by the India Electronics and Semiconductor Association (IESA).

BY AYUSHMAN BARUAH MAY 15, 2025 Share

The Union Cabinet's approval of the INR 3706-crore HCL-Foxconn outsourced semiconductor assembly and test (OSAT) facility under the India Semiconductor Mission is a major fillip for the semiconductor manufacturing industry in India.

The government said that already five semiconductor units are in advanced stages of construction in the country. With this sixth unit, Bharat moves forward in its journey to develop the strategically vital semiconductor industry, Union Minister Ashwini Vaishnaw said during the announcement.

The proposed unit will be located near the upcoming Jewar airport, within the Yamuna Expressway Industrial Development Authority (YEIDA) region. The facility will produce display driver chips for mobile phones, laptops, automobiles, PCs, and various other display-equipped devices. It is designed to handle 20,000 wafers every month, with an output capacity of 36 million units per month.

"With an investment of INR 3,700 crore, the project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain. This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale," said Ashok Chandak, President, IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, is expected to bring world-class expertise in chip packaging and testing—core to the downstream semiconductor supply chain. HCL Group on the other hand is expected to bring robust technology services, engineering strength, and global relationships, and add local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World' with great support from center and states. This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer, automotive, etc.," Chandak added.

India's semiconductor ecosystem is growing rapidly as cutting-edge design infrastructure has been established in several states.

"Students and entrepreneurs in 270 academic institutions and 70 startups are working on world class latest design technologies for developing new products. 20 products developed by the students of these academic students have been taped out by SCL Mohali," Vaishnaw said.

India's semiconductor market is expected to grow from USD 52 billion in 2024 to USD 103.4 billion by 2030, according to a report by the India Electronics and Semiconductor Association (IESA). The report attributes this growth to major sectors including mobile handsets, information technology (IT), telecommunications, consumer electronics, automotive, aerospace, and defence.

Key global players such as Applied Materials and Lam Research have set up operations in India. US-based Applied Materials recently made a USD 50 million investment to establish an R&D facility in Bengaluru. Similarly, Lam Research said it will invest over INR 100 billion (USD 1.2 billion) in the next few years in Karnataka.

In April this year, Axiro Semiconductor, subsidiary of CG Power and Industrial Solutions (part of Murugappa Group), opened a fabless semiconductor design centre in Bengaluru. Axiro said it is poised to fuel innovation across high-impact sectors including 5G/6G, strategic defence, satellite communications, and industrial IoT. CG Power and Industrial Solutions recently invested USD 36 million, marking CG Power's formal entry into the semiconductor design business.

Axiro said its fabless model enables a sharp focus on chip design and IP creation while leveraging global foundries for production, ensuring rapid scalability, cost optimization, and high performance.

Vellayan Subbiah, Chairman of CG Power and Industrial Solutions said that "breakthrough innovations" and an "unwavering commitment to excellence" will continue to propel Axiro Semiconductor forward. The company aims to deliver cutting-edge solutions for AI, automotive, and IoT applications, further accelerating India's integration into the global semiconductor value chain.

Date	15th May
Publication	IT Voice
Link	https://www.itvoice.in/hcl-foxconn-announce-osat-joint-venture-to-strengthen-indias-semiconductor-ecosystem

MAY 15, 2025 · NEWS / TECHNOLOGY NEWS · 2 MINS READ

HCL-FOXCONN ANNOUNCE OSAT JOINT VENTURE TO STRENGTHEN INDIA'S SEMICONDUCTOR ECOSYSTEM

The **Union Cabinet** chaired by the **Prime Minister Shri Narendra Modi** today approved the establishment of one more semiconductor unit under India Semiconductor Mission.

Already five semiconductor units are in advanced stages of construction. With this sixth unit, Bharat moves forward in its journey to develop the strategically vital semiconductor industry.

The unit approved today is a **joint venture of HCL and Foxconn**. HCL has a long history of developing and manufacturing hardware. Foxconn is a global major in electronics manufacturing. Together they will set up a plant near Jewar airport in **Yamuna Expressway Industrial Development Authority or YEIDA.**

This plant will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and myriad of other devices that have display.

The plant is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. Semiconductor industry is now shaping up across the country. World class design facilities have come up in many states across the country. State governments are vigorously pursuing the design firms.

Students and entrepreneurs in **270 academic institutions and 70 startups are working on world class latest design technologies** for developing new products. 20 products developed by the students of these academic students have been taped out by SCL Mohali.

The new semiconductor unit approved today will attract investment of Rs 3,700 crore. As the country moves forward in semiconductor journey, the eco system partners have also established their facilities in India. Applied Materials and Lam Research are two of the largest equipment manufacturers. Both have a presence in India now. **Merck, Linde, Air Liquide, Inox, and many other gas and chemical suppliers are gearing up for growth of our semiconductor industry.**

With the demand for semiconductor increasing with the rapid growth of laptop, mobile phone, server, medical device, power electronics, defence equipment, and consumer electronics manufacturing in Bharat, this new unit will further add to **Prime Minister Shri Narendra Modiji's vision of Atmanirbhar Bharat.**

Ashok Chandak, President IESA and SEMI India

The **Cabinet's approval of the HCL–Foxconn OSAT joint venture** marks a strategic milestone in India's semiconductor journey," *"With an investment of ₹3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.*

This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale." **Commented Ashok Chandak, President IESA and SEMI India.**

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing—core to the downstream semiconductor supply chain. HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for Mobiles, Laptops, Consumer, Automotive, etc. . " Chandak added.

Date	15th May
Publication	Cellit
Link	https://cellit.in/cabinet-approves-rs-3706-cr-hcl-foxconn-semiconductor-plant-in-uttar-pradesh/

CABINET APPROVES RS 3,706 CR HCL-FOXCONN SEMICONDUCTOR PLANT IN UTTAR PRADESH

15th May 2025

The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing — with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday. The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts. "With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs — addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain. HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations —aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

Date	15th May
Publication	Et Insight
Link	https://etedge-insights.com/featured-insights/rs-3700-cr-chip-boost-india-accelerates-semiconductor-push-with-new-hcl-foxconn-unit-in-uttar-pradesh/

Rs 3,700 Cr chip boost: India accelerates semiconductor push with new HCL–Foxconn unit in Uttar Pradesh

Featured Insights / By Poonam Mondal / May 15, 2025

In a decisive stride toward technological self-reliance, the Union Cabinet, chaired by Prime Minister Shri Narendra Modi, has approved the establishment of a sixth semiconductor unit under the India Semiconductor Mission. This newest venture—an advanced chip packaging and testing facility—will be set up in Uttar Pradesh's YEIDA region near Jewar airport, marking a landmark collaboration between Indian tech major HCL and global electronics manufacturing giant Foxconn.

With an investment of ₹3,700 crore, the facility is poised to manufacture display driver chips—vital components that power a wide array of modern electronic devices from smartphones and laptops to automobiles and consumer electronics. The project's approval signals not only the expansion of India's semiconductor manufacturing footprint but also the growing maturity of its electronics ecosystem.

A strategic leap in India's semiconductor journey

This announcement comes as five other semiconductor units across India enter advanced stages of construction. The latest plant will bolster India's downstream semiconductor supply chain, a segment often dominated by East Asian countries. It is a significant step forward in realizing Prime Minister Modi's vision of an "Atmanirbhar Bharat"—a self-reliant India equipped to meet its own high-tech demands.

The proposed facility will have a production capacity of 20,000 wafers per month, with the capability to output 36 million units of display driver ICs monthly. These chips are the silent enablers behind visual displays in nearly all modern digital devices. The decision to manufacture them in India reflects the rising domestic demand across sectors such as mobile devices, personal computing, automotive electronics, medical technology, and defense equipment.

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"As the country moves forward in the semiconductor journey, ecosystem partners have also established their facilities in India," said a senior government official. "Applied Materials and Lam Research—two of the world's largest semiconductor equipment manufacturers—now have a presence in India. Key suppliers of industrial gases and chemicals like Merck, Linde, Air Liquide, and Inox are also preparing for scale."

HCL and Foxconn: A strategic partnership

The collaboration between HCL and Foxconn represents the union of complementary capabilities. While HCL brings its decades-long experience in technology services, hardware engineering, and deep local market insights, Foxconn adds its global leadership in electronics manufacturing and chip packaging. This strategic synergy is expected to deliver industrial-scale capabilities tailored to the growing needs of India's display and electronics sectors.

"This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale," commented Ashok Chandak, President of IESA and SEMI India.

He further emphasized the significance of the project in plugging a critical gap in India's display and electronics value chain: "With an investment of ₹3,700 crore, the project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain."

Foxconn's expertise in chip packaging and testing is central to the downstream semiconductor value chain—an area that requires not just capital, but sophisticated know-how and scale. By pairing with HCL, which offers robust execution capabilities and access to a skilled talent pool, the venture aims to set new benchmarks for domestic manufacturing.

Building a resilient chip ecosystem

India's semiconductor mission is more than a collection of new factories—it is a blueprint to create an integrated, self-sufficient ecosystem encompassing design, fabrication, packaging, testing, and research. The HCL-Foxconn plant will play a critical role in this strategy, particularly by focusing on OSAT (Outsourced Semiconductor Assembly and Test) services. OSAT is a crucial link between chip design and the finished product, and until recently, India had little footprint in this domain.

The approval of this project also complements efforts in other parts of the semiconductor value chain. Across the country, state governments have been working actively to attract design firms and support innovation. World-class design facilities have already been established in several states, and the momentum is visible in academic and startup circles as well.

Currently, over 270 academic institutions and 70 startups are engaged in cutting-edge chip design technologies. Significantly, 20 product designs from these student innovators have been successfully taped out by the Semiconductor Laboratory (SCL) in Mohali—an achievement that underscores the depth of talent and potential in India's semiconductor ecosystem.

The road ahead

India's semiconductor journey has been long-awaited, and while much progress remains to be made, initiatives like the HCL–Foxconn joint venture show that the vision is beginning to crystallize into reality. With global demand for semiconductors soaring and geopolitical realignments altering traditional supply chains, India is seizing the moment to position itself as a formidable player.

Ashok Chandak summed it up well: "Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing—core to the downstream semiconductor supply chain. HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access."

This venture represents not just industrial expansion, but a strategic investment in India's future. It also aligns closely with broader global trends, as countries around the world scramble to secure semiconductor capabilities in the face of ongoing supply disruptions, rising demand for AI hardware, and evolving national security concerns.

The success of the India Semiconductor Mission will depend on how quickly the ecosystem can scale and collaborate. As India lays the foundation stone for yet another critical unit in this journey, it sends a clear message to the world: the future of semiconductors has a new address—and it's rapidly taking shape in Bharat.

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'Trump rhetoric won't harm Apple's India manufacturing'

There is no alarm over the U.S. President's remarks "we don't want you building in India" to CEO Tim Cook, as manufacturing commitments for India and the U.S. are different, say officials here

Updated - May 15, 2025 11:08 pm IST - NEW DELHI

MINI TEJASWI, ARDON DEEP

The Foxconn assembly unit in Sriperumbudur, Tamil Nadu, is among the units through which Apple is serving demand for its phones and accessories.

Apple, Inc.'s existing and soon-to-be-opened infrastructure in India is sufficient to supply demand for iPhones in India and the United States, government sources said, adding that there was not much alarm in India over U.S. President Donald Trump's remarks to Apple CEO Tim Cook that he didn't "want you [Apple] building in India".

"You can build in India if you want to take care of India," Mr. Trump said in Qatar, describing a conversation he had with Mr. Cook, adding that Apple had already committed $500 billion in investments into U.S. manufacturing.

As far as the assembly of iPhones is concerned, demand for both the U.S. and India in the ongoing quarter can be met with capacity from India, and this is infrastructure that is not practical to shift to a high labour-cost country like the U.S., least of all in short order, an official said. The manufacturing commitments that Apple has already made for the U.S. are for chips and other components which are not being made in India, the official added.

An Apple spokesperson declined to comment. The company has assured the Indian government that existing plans will not be impacted by Mr. Trump's remarks.

Apple is serving demand for its phones and accessories through the following units, both existing and being planned to open: the Foxconn assembly unit in Sriperumbudur, the Pegatron facility in Mahindra World City in Chengalpattu, the component manufacturing unit in Krishnagiri, and the new Foxconn facility in Tumkur.

Two of these units — in Tumkur and Krishnagiri — have had their construction completed, and production is likely to start soon. Further manufacturing commitments by the company in India beyond these facilities have not yet been made, an official said, adding that this was only likely to happen after there was more clarity on the bilateral trade agreement being negotiated between India and the U.S.

With global markets witnessing a series of announcements, counter announcements, retractions and course corrections by Washington in the last couple of months, Mr. Trump's latest 'diktat' to Mr. Cook would also fizzle out soon, industry players anticipated.

"How can global corporates change their programmes based on political changes? They work on long-term strategies for diversification, to improve supply chain systems by increasing manufacturing footprint. And, Apple has been doing that in many countries, including in India," remarked Indian Electronics and Semiconductor Association (IESA) [resident Ashok Chandak.

He said he did not anticipate a scenario where Apple would stop producing for exports from India. He, however, said it was not correct to speculate, "rather give it some time, especially when India was in advanced talks with the U.S. on trade agreements."

"Making all iPhones for world markets in the U.S. will make these phones very expensive and unaffordable for most export markets. So, it is not viable for Apple to stop producing phones for exports in India or other cost-effective markets where labour is also available," Mr. Naidu added.

S&P Global Market Intelligence had recently reported that Apple has plans to replace its iPhone sourcing for the U.S. market from mainland China to India by 2026, which may lead to an increase in exports and a greater role for India in global supply chains, despite potential challenges in scaling up production.

Apple's Indian exports, predominantly to the United States, represented 81.9% of phones exported by the firm in the first quarter of calendar 2025, as per data shared by S&P Global Market Intelligence. In March, the export share increased to 97.6%, likely reflecting the firm looking to pre-empt higher tariffs, the financial intelligence and analytics firm said.

"'Whatever happens should be in the interest of both the countries: India and the U.S.,'" Mr. Chandak added.

According to IESA, India's electronics manufacturing sector is already a $150 billion industry and is expected to cross $500 billion by 2030.

B.V. Naidu, an industry (semiconductor, electronics and IT) veteran and managing partner, StartupXseed Ventures, a venture capital firm in Bengaluru, said corporate decisions and footprint expansions were fully-driven by market forces and U.S. President Trump's suggestion would not be feasible for Apple.

According to S&P Global, Apple's move would enhance India's reputation in global supply chains, particularly if a U.S.-India Bilateral Trade Agreement is secured by the third quarter of 2025, despite potential challenges like labour strikes.

Apple's iPhone sales in the U.S. were 75.9 million units in 2024, with exports in March from India equivalent to 3.1 million units, suggesting a need to double shipments either through new capacity or redirecting shipments bound for the domestic market.

In any event, mainland China will remain an important source of phone components for India, having represented 71.3% of shipments in the first quarter of 2025, the firm reported.

Apple assembled $22 billion worth of iPhones in India in the 12 months through March, increasing production by nearly 60% over the previous year.

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Publication	Exclusive News
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Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

New Delhi, May 2025.

The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey," "With an investment of ₹3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs—addressing a critical gap in India's display and electronics value chain.

This isn't just about building infrastructure—it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale." Commented Ashok Chandak, President IESA and SEMI India.

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"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for Mobiles, Laptops, Consumer, Automotive, etc. ." Chandak added.

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Date	14th May
Publication	Ajmer Nama
Link	https://ajmernama.com/national/431416/

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है – जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है।

यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	14th May
Publication	Prokerala
Link	https://www.prokerala.com/news/articles/a1634623.html

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

By IANS | Published on Wed, May 14 2025 16:50 IST

NEW DELHI, MAY 14 : The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing -- with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs -- addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

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"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations —aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

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Home > News > National

Cabinet clears semiconductor unit for Uttar Pradesh

The Hans India
Hans News Service | 15 May 2025 12:53 PM IST

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HIGHLIGHTS

New Delhi: The Union Cabinet, chaired by Prime Minister Narendra Modi, on Wednesday approved the establishment of a semiconductor unit in Uttar...

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The unit is a joint venture of HCL and Foxconn and together, they will set up the plant near Jewar airport in the Yamuna Expressway Industrial Development Authority (YEIDA) area.

The plant is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

According to a Cabinet note, with the demand for semiconductor increasing with the rapid growth of laptop, mobile phone, server, medical device, power electronics, defence equipment, and consumer electronics manufacturing in Bharat, this new unit will further add to Prime Minister Narendra Modi's vision of 'Atmanirbhar Bharat'.

HCL has a long history of developing and manufacturing hardware while Foxconn is a global major in electronics manufacturing.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," said the cabinet.

"Semiconductor industry is now shaping up across the country. World-class design facilities have come up in many states across the country. State governments are vigorously pursuing the design firms," it added in its note.

Students and entrepreneurs in 270 academic institutions and 70 startups are working on world-class latest design technologies for developing new products. Around 20 products developed by the students of these academic students have been taped out by SCL Mohali.

As the country moves forward in semiconductor journey, the ecosystem partners have also established their facilities

in India.

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Publication	Social News XYZ
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HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

POSTED BY: GOPI MAY 14, 2025

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Neel Shirodkar May 14, 2025

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-IANS

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By IANS | Updated: May 14, 2025 16:52 IST

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Link	https://tennews.in/hcl-foxconn-plant-reflects-indias-growing-maturity-in-semiconductor-manufacturing/

BUSINESS

HCL-Foxconn Plant Reflects India's Growing Maturity In Semiconductor Manufacturing

On May 14, 2025

New Delhi, May 14 (IANS) The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing — with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs — addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations —aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

–IANS

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Publication	IANS Live
Link	https://ianslive.in/hcl-foxconn-plant-reflects-indias-growing-maturity-in-semiconductor-manufacturing--20250514164459

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

IANS | May 14, 2025 4:46 PM

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--IANS

Date	14th May
Publication	The Freedom Press
Link	https://thefreedompress.in/index.php/2025/05/14/hcl-foxconn-plant-reflects-indias-growing-maturity-in-semiconductor-manufacturing/

Business

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

TheFreedomPress · 2 days ago · 22 · 1 minute read

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–IANS

Date	14th May
Publication	The Hawk
Link	https://www.thehawk.in/news/science/hcl-foxconn-plant-reflects-indias-growing-maturity-in-semiconductor-manufacturing

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

The Hawk
May 15, 2025, 01:21 PM

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--IANS

Date	14th May
Publication	Outlook Business
Link	https://www.outlookbusiness.com/news/union-cabinet-approves-indias-sixth-chip-unit-worth-rs-3700-cr

News

Union Cabinet Approves India's Sixth Chip Unit Worth Rs 3,700 cr

The new unit will be set up by a joint venture between HCL and Foxconn near the Jewar airport in Yamuna Expressway Industrial Development Authority (YEIDA)

Outlook Business Desk
Updated on: 14 May 2025 5:50 pm

The Union Cabinet on Wednesday approved the establishment of the sixth semiconductor unit under the India Semiconductor Mission. The new unit will be set up by a joint venture between HCL and Foxconn near the Jewar airport in Yamuna Expressway Industrial Development Authority (YEIDA).

The chip plant is estimated to attract an investment of Rs 3,700 crore, the government said in a statement.

This plant will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and myriad of other devices that have display. It is designed for 20,000 wafers per month. The design output capacity is 36 million units per month, the government said.

"Already five semiconductor units are in advanced stages of construction. With this sixth unit, Bharat moves forward in its journey to develop the strategically vital semiconductor industry," the statement added.

HCL has a long history of developing and manufacturing hardware. Foxconn is a global major in electronics manufacturing. Together they will set up a plant near Jewar airport in Yamuna Expressway Industrial Development Authority or YEIDA.

Hailing the approval as a "strategic milestone" in India's semiconductor journey, IESA President Ashok Chandak said the project will address a critical gap in India's display and electronics value chain, bringing large scale advanced packaging and testing capabilities for display driver ICs.

"This joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations —truly aligning with the vision of 'Make in India, Make for the World with great support from center and states,'" Chandak added.

Foxconn, one of the contract manufacturers for Apple, had earlier tried to set up a $19.5 billion joint venture with Vedanta but the plan was set aside in July 2023.

According to industry experts, the local demand for display driver chips that HCL-Foxconn JV will be producing will be huge.

These chips are employed in devices having display such as mobile phones, automobiles, and smartwatches, said Sanjeev Keskar, CEO of Arvind Consultancy.

"About 40% of the Indian electronics market is occupied by smartphones, we make over 20 million two-wheelers, we produce about 5 million cars. All these require display driver chips," Keskar said while highlighting the local demand potential of display driver chips.

Semiconductor industry is now shaping up across the country and world class design facilities have come up in many states, the government said, adding that various state governments are vigorously pursuing the design firms.

As chip manufacturing units are coming up in the country, several ecosystem companies such as Applied Materials and Lam Research are also establishing their facilities in India.

"Applied Materials and Lam Research are two of the largest equipment manufacturers. Both have a presence in India now. Merck, Linde, Air Liquide, Inox, and many other gas and chemical suppliers are gearing up for growth of our semiconductor industry," the government said.

The cabinet approval to the sixth chip unit comes days after reports that the Adani group has paused its talks with Israel's Tower Semiconductors for a $10 billion semiconductor unit in Maharashtra. The plan, according to media reports, was shelved as it did not seem strategic and commercial sense for the group.

India's semiconductor market is estimated to grow from $52 billion (Rs 4.5 trillion) in 2024 to $103.4 billion (Rs 9 trillion) by 2030.

Date	14th May
Publication	Business Line
Link	https://www.thehindubusinessline.com/info-tech/jewar-gets-semiconductor-plant-cabinet-gives-nod-for-indias-sixth-unit/article69574850.ece

INFO-TECH

Cabinet approves ₹3,700-crore HCL-Foxconn semiconductor unit in UP

The semiconductor plant will be set up near Jewar airport in the Yamuna Expressway Industrial Development Authority (YEIDA) in Uttar Pradesh

By BL Bengaluru Bureau

Updated - May 14, 2025 at 06:55 PM | New Delhi, May 14

The Union Cabinet, led by Prime Minister Modi, has approved the setting up of a semiconductor unit under the India Semiconductor Mission. The unit, a joint venture between HCL and Foxconn, is expected to attract an investment of ₹3,700 crore.

The two companies will set up the plant near Jewar airport in the Yamuna Expressway Industrial Development Authority (YEIDA) in Uttar Pradesh.

The plant is designed to manufacture 20,000 wafers each month, with a design output capacity of 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have a display.

According to the Ministry of Electronics and IT, five other semiconductor units are already in advanced stages of construction. HCL has a history of developing and manufacturing hardware, while Foxconn is a major global electronics manufacturer.

Commenting on this, Ashok Chandak, President, IESA and SEMI India, said, "The Cabinet's approval of the HCL–Foxconn OSAT joint venture marks a strategic milestone in India's semiconductor journey. With an investment of ₹3,700 crore, the project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs, addressing a critical gap in India's display and electronics value chain. This isn't just about building infrastructure — it reflects India's growing maturity in semiconductor manufacture, with trusted partners, strategic intent, and industrial scale."

With the demand for semiconductors increasing with the rapid growth of laptops, mobile phones, servers, medical devices, power electronics, defence equipment, and consumer electronics manufacturing in Bharat, this new unit is said to add to the Prime Minister's vision of Atmanirbhar Bharat.

As the country moves forward in semiconductor journey, the eco system partners have also established their facilities in India. Applied Materials and Lam Research are two of the largest equipment manufacturers. Both have a presence in India now. Merck, Linde, Air Liquide, Inox, and many other gas and chemical suppliers are gearing up for growth of our semiconductor industry.

With the demand for semiconductor increasing with the rapid growth of laptop, mobile phone, server, medical device, power electronics, defence equipment, and consumer electronics manufacturing in Bharat, this new unit will further add to India's vision of Atmanirbhar Bharat.

Date	14th May
Publication	Business Standard
Link	https://www.business-standard.com/industry/news/cabinet-clears-hcl-foxconn-chip-assembly-unit-under-india-semiconductor-125051401135_1.html

Cabinet clears ₹3,706 cr HCL-Foxconn chip assembly unit at Jewar

The OSAT unit will assemble 20,000 wafers a month and generate 2,000 jobs; it is the sixth project approved under the India Semiconductor Mission

The Union Cabinet on Wednesday approved the ₹3,706 crore HCL Group-Foxconn joint venture chip assembly unit in Uttar Pradesh's Jewar, Union Electronics and Information Technology Minister Ashwini Vaishnaw said.

The outsourced assembly and testing (OSAT) unit, which is expected to employ 2,000 people, will assemble up to 20,000 wafers per month with a design output capacity of 36 million units per month, the minister added.

"This plant will manufacture display driver chips for mobiles, laptops, personal computers, automobiles, and other electronic devices that need a display unit. This was a requirement for India as electronic manufacturing has risen multifold in recent years. The display driver chip is one of the key components in the ecosystem," Vaishnaw said, adding that the plant will use wafer-level technology to assemble chips.

This is the sixth project that has been approved by the Centre under the India Semiconductor Mission (ISM). The ₹76,000 crore ISM incentive plan, which aimed to kickstart semiconductor chip manufacturing and packaging in the country, has been successful, and has seen six applications approved.

Five of these ISM-approved projects are chip packaging units while Tata Electronics is the sole chip fabrication unit so far. The Tata Group's Dholera semiconductor unit is the sole chip fabrication facility in India, which was approved by the central government on February 29 last year under the ISM.

The plant is expected to start operations by 2027 and may employ nearly 2,000 people. The Dholera chip fabrication unit is coming up at a cost of over ₹91,000 crore.

"With an investment of ₹3,700 crore, the project brings large-scale advanced packaging and testing capabilities specifically for display driver ICs — addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, president of the semiconductor policy advisory bodies, India Electronics and Semiconductor Association and SEMI India.

Date	14th May
Publication	DataQuest
Link	https://www.dqindia.com/esdm/hcl-foxconn-in-osat-joint-venture-9069066

HCL-Foxconn in OSAT joint venture

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"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT operations—truly aligning with the vision of 'Make in India, Make for the World with great support from center and states and This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer, automotive, etc." he added.

Date	14th May
Publication	Democraticjagat
Link	https://democraticjagat.com/news-post/9119/cabinet-approval-for-hcl-foxconn-osat-joint-venture-a-strategic-milestone

Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

New Delhi, May 14, 2025.

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Date	14th May
Publication	Exclusive News
Link	https://exclusivenews.co.in/cabinet-approval-for-hcl-foxconn-osat-joint-venture-a-strategic-milestone/#google_vignette

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May 14, 2025

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Date	14th May
Publication	Divyarashtra
Link	https://divyarashtra.com/cabinet-approval-for-hcl-foxconn-osat-joint-venture-a-strategic-milestone/

Cabinet approval for HCL-Foxconn OSAT joint venture a strategic milestone

By **Divya Rashtra** - May 14, 2025 48 views 0

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Date	14th May
Publication	Bhaskar Live
Link	https://bhaskarlive.in/hcl-foxconn-plant-reflects-indias-growing-maturity-in-semiconductor-manufacturing/

HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

May 14, 2025 14

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Date	14th May
Publication	Ajmernama
Link	https://ajmernama.com/national/431416/

एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी रणनीतिक रूप से एक मील का पत्थर

May 14, 2025 by associate

आईईएसए और सेमि इंडिया के प्रेसिडेंट अशोक चांडक के अनुसार एचसीएल-फॉक्सकॉन ओएसएटी संयुक्त उद्यम को कैबिनेट की मंजूरी मिलना भारत की सेमीकंडक्टर यात्रा में रणनीतिक रूप से एक मील का पत्थर है। 3,700 करोड़ रुपये के निवेश के साथ यह प्रोजेक्ट बड़े पैमाने पर उन्नत पैकेजिंग और परीक्षण क्षमताओं को लेकर आएगा जो खास तौर पर डिस्प्ले ड्राइवर आईसी के लिए होंगे। इससे भारत की डिस्प्ले और इलेक्ट्रॉनिक्स वैल्यू चेन में मौजूद अंतर को दूर करने में मदद मिलेगी। यह सिर्फ इंफ्रास्ट्रक्चर निर्माण के बारे में नहीं है बल्कि यह विश्वसनीय भागीदारों, रणनीतिक इरादे और औद्योगिक पैमाने के साथ सेमीकंडक्टर मैन्युफैक्चरिंग में भारत की बढ़ती परिपक्वता को दर्शाता है। दुनिया के सबसे बड़े इलेक्ट्रॉनिक्स निर्माताओं में से एक फॉक्सकॉन चिप पैकेजिंग और परीक्षण में विश्व स्तरीय विशेषज्ञता लाता है – जो डाउनस्ट्रीम सेमीकंडक्टर सप्लाई चेन का मुख्य हिस्सा है। एचसीएल ग्रुप, अपनी मजबूत प्रौद्योगिकी सेवाओं, इंजीनियरिंग क्षमता और वैश्विक संबंधों के साथ, स्थानीय निष्पादन सामर्थ्य और प्रतिभा तक पहुंच मुहैया कराता है।

यह संयुक्त उपक्रम भारत को सेमीकंडक्टर ओएसएटी परिचालन के वैश्विक केंद्र के रूप में स्थापित करने में नींव का काम करेगा। यह कदम 'मेक इन इंडिया, मेक फॉर द वर्ल्ड' विज़न के मुताबिक है। केन्द्र सरकार और राज्यों के सहयोग से यह परियोजना लैंडमार्क बन सकती है क्योंकि यह मोबाइल, लैपटॉप, कंज़्यूमर गुड्स, ऑटोमोटिव आदि के लिए भारत के इलेक्ट्रॉनिक्स मैन्युफैक्चरिंग में बहुत बड़ा वैल्यू ऐडिशन कर सकती है।

Date	14th May
Publication	Deep Tech
Link	https://analyticsindiamag.com/deep-tech/why-indias-sixth-semiconductor-unit-in-up-holds-the-key-now/

Published on May 14, 2025 • In Deep Tech

Why India's Sixth Semiconductor Unit in UP Holds the Key Now

The plant is expected to handle 20,000 wafers monthly and deliver an output capacity of 36 million units monthly.

India's semiconductor journey, once seen as a distant ambition, is now picking up serious momentum. With strategic policy support, rising domestic demand, and global supply chain realignments, the country is positioning itself as an emerging hub in the global chipmaking ecosystem.

From chip design innovations in academic institutions to infrastructure investments by global majors, the chip manufacturing ecosystem is taking shape. It promises to power everything from smartphones and electric vehicles to defence systems and next-gen computing.

Against this backdrop, the announcement of a sixth semiconductor unit under the India Semiconductor Mission (ISM) aims to bolster the country's strategic capabilities in electronics manufacturing. It signals progress and a deeper commitment to self-reliance in this critical technology sector.

The Union cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of a new semiconductor manufacturing unit in Uttar Pradesh. The plant, to be located near Jewar airport in the Yamuna Expressway Industrial Development Authority (YEIDA) area, will be developed through a joint venture between HCL and Foxconn.

The new facility will produce display driver chips for mobile phones, laptops, PCs, automobiles and other display-based devices.

The plant is expected to handle 20,000 wafers monthly and deliver an output capacity of 36 million units per month, as per the announcement. The venture will also attract an investment of ₹3,700 crore.

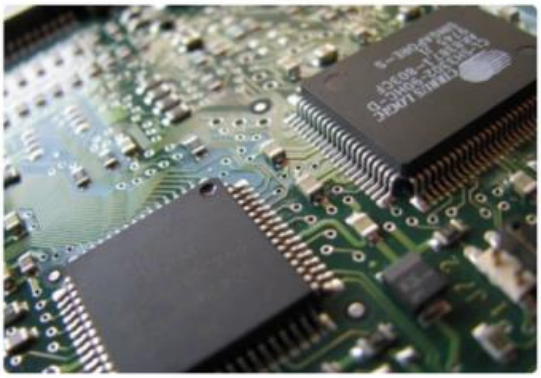
The ISM continues to gain momentum, aligning with the government's vision of a self-reliant manufacturing or Atmanirbhar Bharat. It also adds to the recent announcement that Renesas Electronics will build two design facilities in Noida and Bengaluru, aiming to develop end-to-end 3-nanometer chips.

Ashok Chandak, president of IESA and SEMI India, said, "This isn't just about building infrastructure, it reflects India's growing maturity in semiconductor manufacturing, with trusted partners, strategic intent, and industrial scale."

Chandak also highlighted that the collaboration would position India as a global hub for semiconductor Outsourced Semiconductor Assembly And Test (OSAT) operations, aligning with the vision of "Make in India, Make for the World."

Date	14th May
Publication	Dailyhunt
Link	https://m.dailyhunt.in/news/india/english/sakshipost-epaper-sakshien/hcl+foxconn+plant+reflects+india+s+growing+maturity+in+semiconductor+manufacturing-newsid-n664302370

Sakshi Post



HCL-Foxconn plant reflects India's growing maturity in semiconductor manufacturing

New Delhi, May 14 (IANS) The Cabinet's approval of the HCL-Foxconn chip plant reflects India's growing maturity in semiconductor manufacturing -- with trusted partners, strategic intent and industrial scale, industry experts said on Wednesday.

The Cabinet, chaired by Prime Minister Narendra Modi, has approved the establishment of the semiconductor unit in Uttar Pradesh under the India Semiconductor Mission (ISM) that would attract investment of Rs 3,700 crore.

This marks a strategic milestone in India's semiconductor journey, said experts.

"With an investment of Rs 3,700 crore, the project brings large scale advanced packaging and testing capabilities specifically for display driver ICs -- addressing a critical gap in India's display and electronics value chain," said Ashok Chandak, President IESA and SEMI India.

Foxconn, one of the world's largest electronics manufacturers, brings world-class expertise in chip packaging and testing core to the downstream semiconductor supply chain.

HCL Group, with its robust technology services, engineering strength, and global relationships, adds local execution capability and talent access.

"Together, this joint venture lays the foundation for India to emerge as a preferred global hub for semiconductor OSAT (Outsourced Semiconductor Assembly and Test) operations - aligning with the vision of 'Make in India' and 'Make for the World' with great support from the Centre and states," Chandak said.

The plant near Jewar airport is designed for 20,000 wafers per month. The design output capacity is 36 million units per month. It will manufacture display driver chips for mobile phones, laptops, automobiles, PCs, and other devices that have display.

"This project can become landmark as it can create major value addition in India's electronics manufacturing for mobiles, laptops, consumer and automotive, etc," Chandak noted.

Five semiconductor units are in advanced stages of construction. With this sixth unit, "Bharat moves forward in its journey to develop the strategically vital semiconductor industry," according to the Cabinet.

INDUSTRY STORY – The India–UK free trade agreement FTA

PRINT – JAIPUR

Date	8th May
Publication	Dainik Jalte Deep
Quote By	Ashok Chandak

भारत-यूके के बीच मुक्त व्यापार समझौता

■ जलतेदीप, नई दिल्ली

आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा, ''भारत-यूके मुक्त व्यापार समझौता (एफटीए) वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बड़ाने के लिए उचित समय पर उठाया गया एक प्रेरक कदम है। इससे सर्विस सेक्टर को भी काफी फायदा होगा। संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता । उन्होंने कहा, ''यह समझौता कुशल प्रतिभाओं के आदान-प्रदान की सुविधा प्रदान करेगा, इससे सप्लाई चेन के लचीलेपन में मजबूती आएगी और ग्रीन इलेक्ट्रॉनिक्स सहयोग को बड़ावा मिलेगा।

Date	8th May
Publication	Dainik Dhola Maru
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

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Date	8th May
Publication	Bureau Sandesh
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

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Date	8th May
Publication	Business Remedies
Quote By	Ashok Chandak

जयपुर। गुरूवार 8 मई, 2025

बिज़नेस रेमेडीज

टैक्सटाइल | इंटरनेशनल | हैंडीक्रॉफ्ट

भारत-यूके मुक्त व्यापार समझौत से एआई और स्किलिंग को मिलेगा बढ़ावा: इंडस्ट्री

बिज़नेस रेमेडीज/
नई दिल्ली/आईएएनएस

मुक्त व्यापार समझौता (एफटीए)

मुक्त व्यापार समझौता (एफटीए) ब्रिटेन को एआई के क्षेत्र में अपनी महत्वाकांक्षाओं को प्राप्त करने के लिए अपने छात्रों और प्रतिभाओं के लिए भारत को एक प्रमुख गंतव्य के रूप में मान्यता देगा, यह जानकारी इंडस्ट्री लीडर्स की ओर से बुधवार को दी गई।

भारत और ब्रिटेन के बीच व्यापार समझौता ऐतिहासिक है। इससे दोनों देशों के बीच साझेदारी में बढ़ोतरी होगी। सीआईआई यूके इंडिया बिजनेस फोरम के अध्यक्ष केशव मुरुगेश ने कहा, कि इस समझौते से तत्काल आर्थिक लाभ मिलेगा। इससे वस्तुओं,सेवाओं और विशेष रूप से टेक्नोलॉजी के व्यापार में वृद्धि होगी। एआई जैसे प्रमुख क्षेत्रों में औपचारिक साझेदारी इनोवेशन को बढ़ावा देगी और उच्च कौशल वाली नौकरियों का सृजन करेगी। इस एआई के क्षेत्र में वैश्विक लीडर्स के रूप में यूके और भारत की स्थिति को मजबूत करेगी। उन्होंने आगे कहा कि यह एफटीए विशेष रूप से छात्रों और टेक्नोलॉजी पेशेवरों के लिए डीपटेक और कौशल में गहन सहयोग के लिए एक स्प्रिंगबोर्ड के रूप में काम करेगा। इस साझेदारी की दीर्घकालिक क्षमता बहुत अधिक है। आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा कि एफटीए वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बढ़ाएगा। इससे सर्विस सेक्टर को भी काफी फायदा होगा।

ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा के जरिए ज्वाइंट रिसर्च एवं डेवलपमेंट और पार्टनरशिप से डिजाइन, परीक्षण और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इससे स्टार्टअप और इनोवेटर्स को मदद मिलेगी। चांडक के मुताबिक, 'कंपोनेंट, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ घटने से उत्पादन लागत में कमी आएगी और 'मेड इन इंडिया' को सपोर्ट मिलेगा।'

भारत-ब्रिटेन एफटीए से देश से यूके होने वाले 99 प्रतिशत निर्यात पर जीरो शुल्क लगेगा। इसके बदल में भारत धीरे-धीरे ब्रिटेन के 90 प्रतिशत सामानों से शुल्क हटा देगा और अगले दशक में 85 प्रतिशत सामान टैरिफ मुक्त हो जाएंगे। माना जा रहा है कि इस समझौते से आने वाले वर्षों में दोनों देश के बीच व्यापार 60 अरब डॉलर से दोगुना होकर 120 अरब डॉलर तक पहुंचने की उम्मीद है।

Date	8th May
Publication	Dainik News Jyoti
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

न्यूज ज्योति संवाददाता

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Date	8th May
Publication	Dainik Taj Bharti
Quote By	Ashok Chandak

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Date	8th May
Publication	Uday Today
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

जयपुर,(उदय टुडे)। आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा, ''भारत-यूके मुक्त व्यापार समझौता (एफ्टीए) वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बढ़ाने के लिए उचित समय पर उठाया गया एक प्रेरक कदम है। इससे सर्विस सेक्टर को भी काफी फायदा होगा। संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता ।''उन्होंने कहा, ''यह समझौता कुशल प्रतिभाओं के आदान-प्रदान की सुविधा प्रदान करेगा, इससे सप्लाई चेन के लचीलेपन में मजबूती आएगी और ग्रीन इलेक्ट्रॉनिक्स सहयोग को बढ़ावा मिलेगा। इसकी अहमियत यह भी है कि इससे भविष्य के व्यापार समझौतों के लिए एक बेंचमार्क स्थापित हो जाएगा। यह कदम एक समान विचारधारा वाले लोकतंत्रों के साथ जुड़ने के लिए भारत की प्रतिबद्धता को दर्शाता है। इसके फलस्वरूप, देश के कोर सेक्टरों और वैश्विक स्तर पर उच्च तकनीक और रणनीतिक क्षेत्रों में अपनी बात रखने के मामले में भारत की स्थिति पुख्ता बनेगी।

Date	8th May
Publication	Dainik Badti Duniya
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

बढ़ती दुनिया

नई दिल्ली। आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा, ''भारत-यूके मुक्त व्यापार समझौता (एफटीए) वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बढ़ाने के लिए उचित समय पर उठाया गया एक प्रेरक कदम है। इससे सर्विस सेक्टर को भी काफी फायदा होगा। संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता।'

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Date	8th May
Publication	Police Public Politics
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

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संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता।''

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यह कदम एक समान विचारधारा वाले लोकतंत्रों के साथ जुड़ने के लिए भारत की प्रतिबद्धता को दर्शाता है।

इसके फलस्वरूप, देश के कोर सेक्टरों और वैश्विक स्तर पर उच्च तकनीक और रणनीतिक क्षेत्रों में अपनी बात रखने के मामले में भारत की स्थिति पुख्ता बनेगी।''

INDUSTRY STORY – The India – UK free trade agreement FTA

PRINT Jaipur

Date	8th May
Publication	Dainik Jalte Deep
Quote By	Ashok Chandak

भारत-यूके के बीच मुक्त व्यापार समझौता

■ जलतेदीप, नई दिल्ली

आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा, ''भारत-यूके मुक्त व्यापार समझौता (एफटीए) वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बड़ाने के लिए उचित समय पर उठाया गया एक प्रेरक कदम है। इससे सर्विस सेक्टर को भी काफी फायदा होगा। संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता । उन्होंने कहा, ''यह समझौता कुशल प्रतिभाओं के आदान-प्रदान की सुविधा प्रदान करेगा, इससे सप्लाई चेन के लचीलेपन में मजबूती आएगी और ग्रीन इलेक्ट्रॉनिक्स सहयोग को बड़ावा मिलेगा।

Date	8th May
Publication	Dainik Dhola Maru
Quote By	Ashok Chandak

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

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INDUSTRY STORY – The India – UK free trade agreement FTA

ONLINE

Date	7th May
Publication	Democratic Jagat
Link	https://democraticjagat.com/news-post/9108/the-india-uk-free-trade-agreement-to-enhance-the-export-potential-of-made-in-india-products

The India–UK Free Trade Agreement to enhance the export potential of 'Made in India' products

New Delhi, May 2025.

"The India–UK Free Trade Agreement (FTA) is a timely catalyst for boosting the India's image and business opportunities globally in multiple sectors," said Ashok Chandak, President, IESA and SEMI India. The services sector will also benefit significantly, with growth in design, testing, and embedded software, driven by joint R&D and collaboration—leveraging the UK's design strengths and India's engineering talent thereby helping start up's and innovators." "By reducing tariffs on components, raw materials, and capital equipment, it lowers production costs and enhances the export potential of 'Made in India' products

He added, " It facilitates skilled talent exchange, strengthens supply chain resilience, and promotes green electronics collaboration. Importantly, it sets a benchmark for future trade agreements, signalling India's commitment to align with like-minded democracies and boosting its negotiating position in India's core sectors and also high-tech and strategic sectors globally."

Date	7th May
Publication	Exclusive News
Link	https://exclusivenews.co.in/the-india-uk-free-trade-agreement-to-enhance-the-export-potential-of-made-in-india-products/

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Date	7th May
Publication	Divya Rashtra
Link	https://divyarashtra.com/the-india-uk-free-trade-agreement-to-enhance-the-export-potential-of-made-in-india-products/

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Date	7th May
Publication	Ajmer Nama
Link	https://ajmernama.com/national/431077/

भारत-यूके मुक्त व्यापार समझौता से भारत-यूके मुक्त व्यापार समझौता

नई दिल्ली, मई 2025: आईईएसए और सेमी इंडिया के अध्यक्ष अशोक चांडक ने कहा, ''भारत-यूके मुक्त व्यापार समझौता (एफटीए) वैश्विक स्तर पर भारत की छवि और व्यापार के अवसरों को बढ़ाने के लिए उचित समय पर उठाया गया एक प्रेरक कदम है। इससे सर्विस सेक्टर को भी काफी फायदा होगा। संयुक्त आर एंड डी (अनुसंधान एवं विकास) तथा सहयोग से डिजाइन, टैस्टिंग और एम्बेडेड सॉफ्टवेयर में वृद्धि होगी। इस तरह से ब्रिटेन की डिजाइन क्षमता और भारत की इंजीनियरिंग प्रतिभा का लाभ मिलेगा, जिससे स्टार्ट अप और इनोवेटर्स को मदद मिलेगी। कम्पोनेंट्स, कच्चे माल और पूंजीगत उपकरणों पर टैरिफ कम करने से उत्पादन लागत कम होगी और भारत-यूके मुक्त व्यापार समझौता ।''

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INDUSTRY STORY – SEMI IESA applauds Tamil Nadu for the rapid follow-up policy of ECMS

PRINT Chennai

Date	3rd May
Publication	Dina Bhoomi
Quote By	Ashok Chandak

தமிழ்நாடு அரசின் மின்னணு கொள்கைக்கு செமி ஐ.இ.எஸ்.ஏ. பாராட்டு

சென்னை, மே 03-

மத்திய அமைச்சர் ஸ்ரீ வைஷ்ணவ் மின்னணு துறைக்கான தனி இணையதளம் மற்றும் மின்னணு உபகரண உற்பத்தித் திட்டத்துக்கான வழிகாட்டுதலை வெளியிட்ட சில நாளிலேயே தமிழ்நாடு அரசு மின்னணு கொள்கையை வெளியிட்டுள்ளதை செமி ஐஇஎஸ்ஏ பாராட்டி வரவேற்றுள்ளது. இந்தியாவின் மின்னணுவியல் உற்பத்தி சுற்றுச் சூழல் அமைப்பை வலுப்படுத்துவதற்கும், செமி கண்டக்டர் தொலைநோக்கு இலக்கை எட்டுவதற்கான தேசிய முயற்சிகளை எட்டும் வகையில் உள்நாட்டு மதிப்பு கூட்டலை மேம்படுத்தும் வகையில் இந்த நடவடிக்கை அமைந்துள்ளது.

2024-25-ம் நிதிஆண்டில் 14 பில்லியின் அளவுக்கு மின்னணு ஏற்றுமதியில் முன்னணி மாநிலமாக விளங்கிய தமிழ்நாடு, மின்னணு உற்பத்தியில் முன்னேறிய மாநிலமாக தொடர்ந்து தக்கவைத்துக் கொள்வதற்கான தலைமைத்துவத்தை கொள்கைகள் வாயிலாக வெளிப்படுத்தி வருகிறது. மின்னணு உதிரிபாக உற்பத்திக்கு ஏற்ற சூழமைவை மாநிலத்தில் ஏற்படுத்தி, அதற்குத் தேவையான சங்கிலித் தொடர் ஆதரவை ஒரு முனையிலிருந்து மறு முனைவரை வழங்கும் நடவடிக்கைகளை அரசு எடுத்துள்ளது. ஏப்ரல் 26-ம் தேதி அன்று எம்இஐடிஒய் திட்ட வெளியீட்டின்போது ஐஇஎஸ்ஏ அமைப்பால் முன்னிலைப்படுத்தப்பட்டபடி இசிஎம்எஸ்-ன் தாக்கத்தை அதிகப்படுத்துவதற்கான செயலில் மாநில அளவிலான செயல்பாடு மிகவும் முக்கியமானதாகிறது. இதில் தமிழ்நாடு அரசு உயரிய அளவுகோலை நிர்ணயித்துள்ளது. மேலும் பல மாநிலங்கள் ஏற்கெனவே பயனுள்ள வெளியீடுகள் மற்றும் தொழில்துறை வளர்ச்சியை நோக்கி முன்னேறி வருகின்றன.

செமி ஐஇஎஸ்ஏ மற்றும் உறுப்பினர்கள் இசிஎம்எஸ் -ஐ முழுமையாக செயல்படுத்துவதற்கு உரிய ஒத்துழைப்பை மாநில அளவில் அளிப்பதாக ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா அமைப்பின் தலைவர் அசோக் சந்தக் தெரிவித்தார். இசிஎம் எஸ் மற்றும் உற்பத்தியுடன் இணைந்த ஊக்கத் தொகை (பிஎல்ஐ) திட்டம் ஒருங்கிணைந்து செயல்படுத்தப்படுவதன் மூலம் செமிகான் இந்தியா திட்ட இலக்கை எட்ட முடியும் அத்துடன் இதன் மூலம் சர்வதேச அளவில் இந்திய நிறுவனங்கள் போட்டியிடுவதற்கான சூழலும் உருவாகியுள்ளது. செமிகான் இந்தியா திட்டம் மற்றும் முற்போக்கான மாநில அரசின் முன்முயற்சிகள் ஆகியவை இந்தியாவின் மின்னணு துறை மற்றும் செமி கண்டக்டர் உற்பத்தித் துறைகளுக்கு உலகளாவிய போட்டித் தன்மை கொண்ட ஸ்திரமான நன்மையை உருவாக்கும்.

Date	2nd May
Publication	Tamil Sundar
Quote By	Ashok Chandak

தமிழ்நாடு அரசின் மின்னணு கொள்கைக்கு செமி ஐஇஎஸ்ஏ பாராட்டு

சென்னை, மே.2

மத்திய அமைச்சர் ஸ்ரீ வைஷ்ணவ் மின்னணு துறைக்கான தனி இணையதளம் மற்றும் மின்னணு உபகரண உற்பத்தித் திட்டத்துக்கான வழிகாட்டுதலை வெளியிட்ட சில நாளிலேயே தமிழ்நாடு அரசு மின்னணு கொள்கையை வெளியிட்டுள்ளதை செமி ஐஇஎஸ்ஏ பாராட்டி வரவேற்றுள்ளது.

2024-25-ம் நிதி ஆண்டில் 14 பில்லியின் அளவுக்கு மின்னணு ஏற்றுமதியில் முன்னணி மாநிலமாக விளங்கிய தமிழ்நாடு, மின்னணு உற்பத்தியில் முன்னேறிய மாநிலமாக தொடர்ந்து தக்கவைத்துக் கொள்வதற்கான தலைமைத்துவத்தை கொள் கைகள் வாயிலாக வெளிப்படுத்தி வருகிறது. மின்னணு உதிரி பாக உற்பத்திக்கு ஏற்ற சூழமைவை மாநிலத்தில் ஏற்படுத்தி, அதற்குத் தேவையான சங்கிலித் தொடர் ஆதரவை ஒரு முனை யிலிருந்து மறு முனைவரை வழங்கும் நடவடிக்கைகளை அரசு எடுத்துள்ளது. ஏப்ரல் 26-ம் தேதி அன்று எம்இஐடிஒய் திட்ட வெளியீட்டின்போது ஐஇஎஸ்ஏ அமைப்பால் முன்னிலைப்ப டுத்தப்பட்டபடி இசிஎம்எஸ்-ன் தாக்கத்தை அதிகப்படுத்துவ தற்கான செயலில் மாநில அளவிலான செயல்பாடு மிகவும் முக்கியமானதாகிறது. .

``செமி ஐஇஎஸ்ஏ மற்றும் உறுப்பினர்கள் இசிஎம்எஸ் -ஐ முழுமையாக செயல்படுத்துவதற்கு உரிய ஒத்துழைப்பை மாநில அளவில் அளிப்பதாக ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா அமைப்பின் தலைவர் அசோக் சந்தக் தெரிவித்தார். இசிஎம் எஸ் மற்றும் உற்பத்தியுடன் இணைந்த ஊக்கத் தொகை (பிஎ ல்ஐ) திட்டம் ஒருங்கிணைந்து செயல்படுத்தப்படுவதன் மூலம் செமிகான் இந்தியா திட்ட இலக்கை எட்ட முடியும் அத்துடன் இதன் மூலம் சர்வதேச அளவில் இந்திய நிறுவனங்கள் போட் டியிடுவதற்கான சூழலும் உருவாகியுள்ளது.

Date	2nd May
Publication	Virtual Time
Quote By	Ashok Chandak

SEMI IESA Applauds Tamil Nadu for Rapid follow up policy of ECMS

SEMI IESA commends the State of Tamil Nadu for its swift announcement of the State Electronics Components Manufacturing Scheme (ECMS), just days after the release of the central guidelines and portal by Hon'ble Union Minister Shri Ashwini Vaishnaw. This timely action marks a significant step toward strengthening India's electronics manufacturing ecosystem and enhancing domestic value addition — complementing national efforts under the Semiconductor Mission.

Tamil Nadu, which led the nation in electronics exports with $14 billion in 2024–25, continues to demonstrate leadership as a progressive state in electronics manufacturing. Establishing a robust components ecosystem within the state will significantly boost the value chain and support end-to-end manufacturing.

As highlighted by IESA during the MeitY scheme launch on April 26, proactive state-level engagement is key to maximizing the impact of ECMS. Tamil Nadu has set a benchmark, and several other states are already advancing toward effective policy rollouts and industrial development.

"SEMI IESA and our members are fully committed to supporting ECMS through active state-level collaboration," said Ashok Chandak, President, IESA and SEMI India. "The synergy of the ECMS and electronics PLI schemes, the Semicon India program, and progressive state government initiatives will create a globally competitive, sustainable advantage for India's electronics and semiconductor manufacturing sectors."

Date	2nd May
Publication	Maalai Yugan
Quote By	Ashok Chandak

தமிழ்நாடு அரசின் மின்னணு கொள்கைக்கு செமி ஐஇஎஸ்ஏ பாராட்டு

சென்னை, மே.02– மாண்புமிகு மத்திய அமைச்சர் ஸ்ரீ வைஷ்ணவ் மின்னணு துறைக்கான தனி இணையதளம் மற்றும் மின்னணு உபகரண உற்பத்தித் திட்டத்துக்கான வழிகாட்டுதலை வெளியிட்ட சில நாளிலேயே தமிழ்நாடு அரசு மின்னணு கொள்கையை வெளியிட்டுள்ளதை செமி ஐஇஎஸ்ஏ பாராட்டி வரவேற்றுள்ளது. இந்தியாவின் மின்னணுவியல் உற்பத்தி சுற்றுச் சூழல் அமைப்பை வலுப்படுத்துவதற்கும், செமி கண்டக்டர் தொலைநோக்கு இலக்கை எட்டுவதற்கான தேசிய முயற்சிகளை எட்டும் வகையில் உள்நாட்டு மதிப்பு கூட்டலை மேம்படுத்தும் வகையில் இந்த நடவடிக்கை அமைந்துள்ளது.

2024 25ம் நிதி ஆண்டில் 14 பில்லியின் அளவுக்கு மின்னணு ஏற்றுமதியில் முன்னணி மாநிலமாக விளங்கிய தமிழ்நாடு, மின்னணு உற்பத்தியில் முன்னேறிய மாநிலமாக தொடர்ந்து தக்கவைத்துக் கொள்வதற்கான தலைமைத்துவத்தை கொள்கைகள் வாயிலாக வெளிப்படுத்தி வருகிறது. மின்னணு உதிரிபாக உற்பத்திக்கு ஏற்ற சூழமைவை மாநிலத்தில் ஏற்படுத்தி, அதற்குத் தேவையான சங்கிலித் தொடர் ஆதரவை ஒரு முனையிலிருந்து மறு முனைவரை வழங்கும் நடவடிக்கைகளை அரசு எடுத்துள்ளது. ஏப்ரல் 26ம் தேதி அன்று எம்இஐடிஒய் திட்ட வெளியீட்டின்போது ஐஇஎஸ்ஏ அமைப்பால் முன்னிலைப்படுத்தப்பட்டபடி இசிஎம்எஸ்ன் தாக்கத்தை அதிகப்படுத்துவதற்கான செயலில் மாநில அளவிலான செயல்பாடு மிகவும் முக்கியமானதாகிறது. இதில் தமிழ்நாடு அரசு உயரிய அளவுகோலை நிர்ணயித்துள்ளது. மேலும் பல மாநிலங்கள் ஏற்கெனவே பயனுள்ள வெளியீடுகள் மற்றும் தொழில்துறை வளர்ச்சியை நோக்கி முன்னேறி வருகின்றன.

``செமி ஐஇஎஸ்ஏ மற்றும் உறுப்பினர்கள் இசிஎம்எஸ் ஐ முழுமையாக செயல்படுத்துவதற்கு உரிய ஒத்துழைப்பை மாநில அளவில் அளிப்பதாக ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா அமைப்பின் தலைவர் அசோக் சந்தக் தெரிவித்தார். இசிஎம்எஸ் மற்றும் உற்பத்தியுடன் இணைந்த ஊக்கத் தொகை (பிஎல்ஐ) திட்டம் ஒருங்கிணைந்து செயல்படுத்தப்படுவதன் மூலம் செமிகான் இந்தியா திட்ட இலக்கை எட்ட முடியும் அத்துடன் இதன் மூலம் சர்வதேச அளவில் இந்திய நிறுவனங்கள் போட்டியிடுவதற்கான சூழலும் உருவாகியுள்ளது. செமிகான் இந்தியா திட்டம் மற்றும் முற்போக்கான மாநில அரசின் முன்முயற்சிகள் ஆகியவை இந்தியாவின் மின்னணு துறை மற்றும் செமிகண்டக்டர் உற்பத்தித் துறைகளுக்கு உலகளாவிய போட்டித் தன்மை கொண்ட ஸ்திரமான நன்மையை உருவாக்கும்.''

Date	2nd May
Publication	Dina Kathir
Quote By	Ashok Chandak

தமிழ்நாடு அரசின் மின்னணு கொள்கைக்கு செமி ஐஇஎஸ்ஏ பாராட்டு

சென்னை, மே 2: மத்திய அமைச்சர் ஸ்ரீ வைஷ்ணவ் மின்னணு துறைக்கான தனி இணையதளம் மற்றும் மின்னணு உபகரண உற்பத்தித் திட்டத்துக்கான வழிகாட்டுதலை வெளியிட்ட சில நாளிலேயே தமிழ்நாடு அரசு மின்னணு கொள்கையை வெளியிட்டுள்ளதை செமி ஐஇஎஸ்ஏ பாராட்டி வரவேற்றுள்ளது. இந்தியாவின் மின்னணுவியல் உற்பத்தி சுற்றுச் சூழல் அமைப்பை வலுப்படுத்துவதற்கும், செமி கண்டக்டர் தொலைநோக்கு இலக்கை எட்டுவதற்கான தேசிய முயற்சிகளை எட்டும் வகையில் உள்நாட்டு மதிப்பு கூட்டலை மேம்படுத்தும் வகையில் இந்த நடவடிக்கை அமைந்துள்ளது.

2024-25-ம் நிதிஆண்டில் 14 பில்லியின் அளவுக்கு மின்னணு ஏற்றுமதியில் முன்னணி மாநிலமாக விளங்கிய தமிழ்நாடு, மின்னணு உற்பத்தியில் முன்னேறிய மாநிலமாக தொடர்ந்து தக்கவைத்துக் கொள்வதற்கான தலைமைத்துவத்தை கொள்கைகள் வாயிலாக வெளிப்படுத்தி வருகிறது. மின்னணு உதிரிபாக உற்பத்திக்கு ஏற்ற சூழமைவை மாநிலத்தில் ஏற்படுத்தி, அதற்குத் தேவையான சங்கிலித் தொடர் ஆதரவை ஒரு முனையிலிருந்து மறு முனைவரை வழங்கும் நடவடிக்கைகளை அரசு எடுத்துள்ளது. ஏப்ரல் 26-ம் தேதி அன்று எம்இஐடிஒய் திட்ட வெளியீட்டின்போது ஐஇஎஸ்ஏ அமைப்பால் முன்னிலைப்படுத்தப்பட்டபடி இசிஎம்எஸ்-ன் தாக்கத்தை அதிகப்படுத்துவதற்கான செயலில் மாநில அளவிலான செயல்பாடு மிகவும் முக்கியமானதாகிறது. இதில் தமிழ்நாடு அரசு உயரிய அளவுகோலை நிர்ணயித்துள்ளது. மேலும் பல மாநிலங்கள் ஏற்கெனவே பயனுள்ள வெளியீடுகள் மற்றும் தொழில்துறை வளர்ச்சியை நோக்கி முன்னேறி வருகின்றன.

``செமி ஐஇஎஸ்ஏ மற்றும் உறுப்பினர்கள் இசிஎம்எஸ் -ஐ முழுமையாக செயல்படுத்துவதற்கு உரிய ஒத்துழைப்பை மாநில அளவில் அளிப்பதாக ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா அமைப்பின் தலைவர் அசோக் சந்தக் தெரிவித்தார். இசிஎம் எஸ் மற்றும் உற்பத்தியுடன் இணைந்த ஊக்கத் தொகை (பிஎல்ஐ) திட்டம் ஒருங்கிணைந்து செயல்படுத்தப்படுவதன் மூலம் செமிகான் இந்தியா திட்ட இலக்கை எட்ட முடியும் அத்துடன் இதன் மூலம் சர்வதேச அளவில் இந்திய நிறுவனங்கள் போட்டியிடுவதற்கான சூழலும் உருவாகியுள்ளது. செமிகான் இந்தியா திட்டம் மற்றும் முற்போக்கான மாநில அரசின் முன்முயற்சிகள் ஆகியவை இந்தியாவின் மின்னணு துறை மற்றும் செமி கண்டக்டர் உற்பத்தித் துறைகளுக்கு உலகளாவிய போட்டித் தன்மை கொண்ட ஸ்திரமான நன்மையை உருவாக்கும்.''

Date	1st May
Publication	Dina Kural
Quote By	Ashok Chandak

தின குரல்

தமிழ்நாடு அரசின் மின்னணு கொள்கைக்கு செமி ஐஇஎஸ்ஏ பாராட்டு

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"செமி ஐஇஎஸ்ஏ மற்றும் உறுப்பினர்கள் இசிஎம்எஸ் -ஐ முழுமையாக செயல்படுத்துவதற்கு உரிய ஒத்துழைப்பை மாநில அளவில் அளிப்பதாக ஐஇஎஸ்ஏ மற்றும் செமி இந்தியா அமைப்பின்தலைவர் அசோக்சந்தக்தெரிவித்தார்.இசிஎம்எஸ் மற்றும் உற்பத்தியுடன் இணைந்த ஊக்கத் தொகை (பிஎல்ஐ) திட்டம் ஒருங்கிணைந்து செயல்படுத்தப்படுவதன் மூலம் செமிகான் இந்தியா திட்ட இலக்கை எட்ட முடியும் அத்துடன் இதன் மூலம் சர்வதேச அளவில் இந்திய நிறுவனங்கள் போட்டியிடுவதற்கான சூழலும் உருவாகியுள்ளது. செமிகான் இந்தியா திட்டம் மற்றும் முற்போக்கான மாநில அரசின் முன்முயற்சிகள் ஆகியவை இந்தியாவின் மின்னணு துறை மற்றும் செமி கண்டக்டர் உற்பத்தித் துறைகளுக்கு உலகளாவிய போட்டித் தன்மை கொண்ட ஸ்திரமான நன்மையை உருவாக்கும்."

Date	1st May
Publication	Business Minute
Quote By	Ashok Chandak

SEMI IESA Applauds Tamil Nadu for Rapid follow up policy of ECMS

CHENNAI

SEMI IESA commends the State of Tamil Nadu for its swift announcement of the State Electronics Components Manufacturing Scheme (ECMS), just days after the release of the central guidelines and portal by Union Minister Shri Ashwini Vaishnaw. This timely action marks a significant step toward strengthening India's electronics manufacturing ecosystem and enhancing domestic value addition — complementing national efforts under the Semiconductor Mission.

Tamil Nadu, which led the nation in electronics exports with $14 billion in 2024–25, continues to demonstrate leadership as a progressive state in electronics manufacturing.

Establishing a robust components ecosystem within the state will significantly boost the value chain and support end-to-end manufacturing.

As highlighted by IESA during the MeitY scheme launch on April 26, proactive state-level engagement is key to maximizing the impact of ECMS. Tamil Nadu has set a benchmark, and several other states are already advancing toward effective policy rollouts and industrial development.

"SEMI IESA and our members are fully committed to supporting ECMS through active state-level collaboration," said Ashok Chandak, President, IESA and SEMI India. "The synergy of the ECMS and electronics PLI schemes, the Semicon India program, and progressive state government initiatives will create a globally competitive, sustainable advantage for India's electronics and semiconductor manufacturing sectors."

Date	1st May
Publication	Southern Mail
Quote By	Ashok Chandak

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INDUSTRY STORY – SEMI IESA applauds Tamil Nadu for rapid follow-up policy of ECMS

ONLINE

Date	2nd May
Publication	Chenna Glitz
Link	https://chennaiglitz.com/semi-iesa-applaud s-tamil-nadu-for-rapid-follow-up-policy-of-ecms/

HOME

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ADMINISTRATOR MAY 2, 2025

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Date	1st May
Publication	Express News
Link	https://expressnews.asia/2025/05/semi-iesa-applauds-tamil-nadu-for-rapid-follow-up-policy-of-ecms/

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admin 4 weeks ago Business Comments Off

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Date	30th April
Publication	Times India
Link	https://timesofindia.indiatimes.com/city/chennai/tn-launches-electronics-components-manufacturing-scheme/articleshow/120772357.cms

TN launches electronics components manufacturing scheme

TRB Rajaa

CHENNAI: The Tamil Nadu govt on Wednesday launched an incentive scheme in line with the Union govt's programme to attract global and Indian electronics component manufacturing companies. The `Tamil Nadu Electronics Components Manufacturing Scheme' will provide a matching grant to companies approved under Union govt's incentive package and the govt expects it to bring in Rs30,000 crore investments and create 60,000 jobs.

After the scheme was launched by chief minister M K Stalin, industries minister T R B Raaja told the press, "The scheme will target to attract 11 broad categories of components, including display and camera modules, printed circuit boards (PCBs), flexi PCBs, high density interface boards, lithium-ion battery cells, SMD passive components. This scheme targets machinery used in component making and supply chain infrastructure, along with sub-assemblies and bare components."

> Tamil Nadu leads the country in electronics exports at $14.65 billion in 2024-25 and this initiative is expected to further boost the sector and help us reach the target of $100 billion, Rajaa said.

The Union ministry of electronics and information technology's electronics component manufacturing scheme (ECMS) aims at promoting non-semiconductor components. Establishing a components ecosystem within the state will significantly boost the value chain and proactive state-level engagement is key to maximising the impact of ECMS, said Ashok Chandak, president of India Electronics and Semiconductor Association (IESA). The synergy of the various central and state schemes will create a globally competitive, sustainable advantage, he added.

Higher cost of logistics, finance and capex have hindered establishment of a domestic electronics component ecosystem with a NITI Aayog report estimating cost disability of up to 18% for components. The subsidies are expected to help manufacturers overcome disabilities and achieve economies of scale.

THANK YOU